

客户图

NOTES:

- FINISH:
 - HOUSING: LCP,UL94V-0,BLACK
 - COVER: LCP,UL94V-0,BLACK
 - CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA
- ELECTRICAL:
 - CURRENT RATING: SIGNAL PIN 1.0A.
POWER PIN 30A.
 - DIELECTRIC WITHSTANDING VOLTAGE: SIGNAL PIN 500V DC/MINUTE.
POWER PIN 1000V DC/MINUTE.
 - CONTACT RESISTANCE: SIGNAL PIN 45mΩ MAX.AT DC 20mA.
POWER PIN 2mΩ MAX.AT DC 20mA.
 - INSULATION RESISTANCE: SIGNAL PIN 500V DC/1000MΩ MIN
POWER PIN 500V DC/5000MΩ MIN
- SALT SPRAY TEST:
 - CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST
- MAX PROCESSING TEMP:265°C SECONDS 10S
- OPERATION TEMPERATURE:-40°C TO +105°C.
- ORDER INFORMATION:

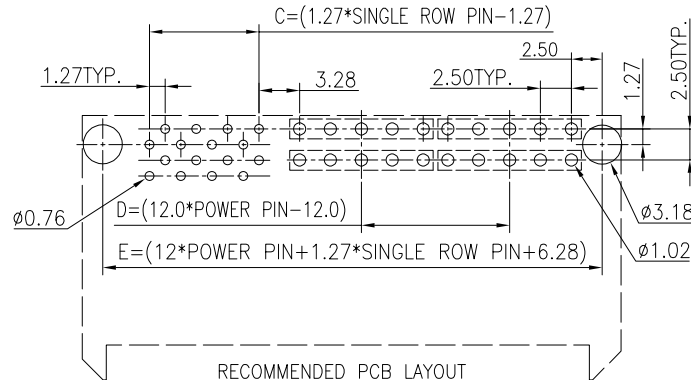
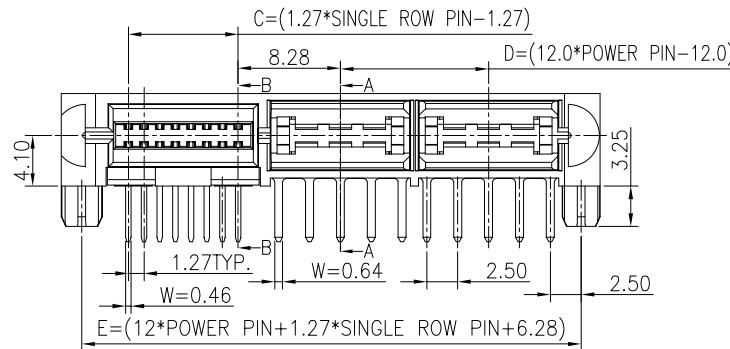
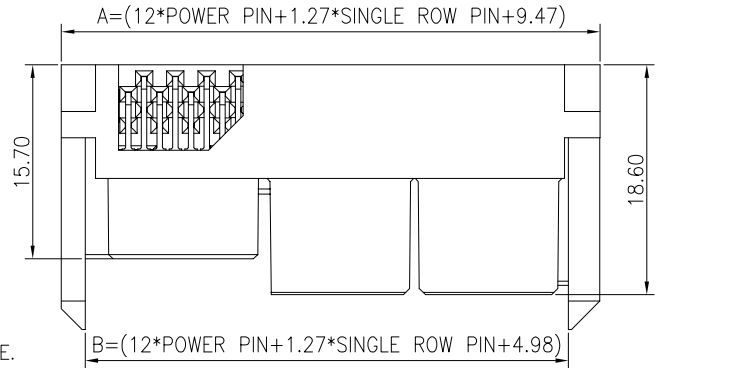
62F4-F XX XXX S4 075 C 0X

流水码:
01=2.90("P")
02=3.60("P")
03=4.50("P")

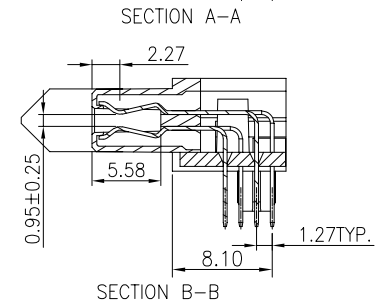
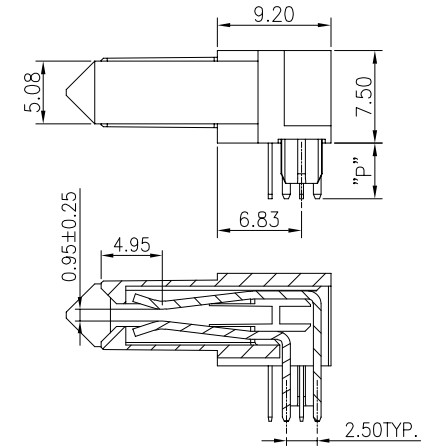
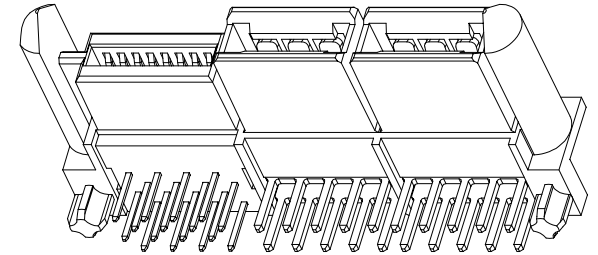
电源Pin数 信号Pin数 端子电镀: 塑胶高度:
002=2*01PIN 012=2*06PIN S0=Gold Flash/Tin 075=7.50mm
(半金锡)

012=2*06PIN 040=2*20PIN S1=1u" Gold/Tin
S2=3u" Gold/Tin
S3=5u" Gold/Tin
S4=10u" Gold/Tin
S5=15u" Gold/Tin
S6=30u" Gold/Tin

流水码	"P" 焊脚长度	PCB 厚度
01	2.90	1.57
02	3.60	2.36
03	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05



					OPERATION		DRAW		Mr.Zeng		2025.03.17		SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					X.X	±0.40	DESIGN		Jensen		2025.03.17					
					X.XX	±0.25	CHECK		Jack		2025.03.17		SIZE	A4	PART NO.	62F4-F XX XXX S4 075 C 0X
A0		NEW			X.XXX	±0.15	APPROVE		Andy		2025.03.17		SHEET	1/1	TITLE:	母座 电源+信号连接器 卧式30° DIP 带导柱 带定位柱
					Angle	±3°										
REV	DATE	MODIFICATION DESCRIPTION		CHANGE	APPROVE	DIM.	TOL	UNIT		mm	SCALE	1:1	PROJ.		DRAW NO.	SP-1470

客户图

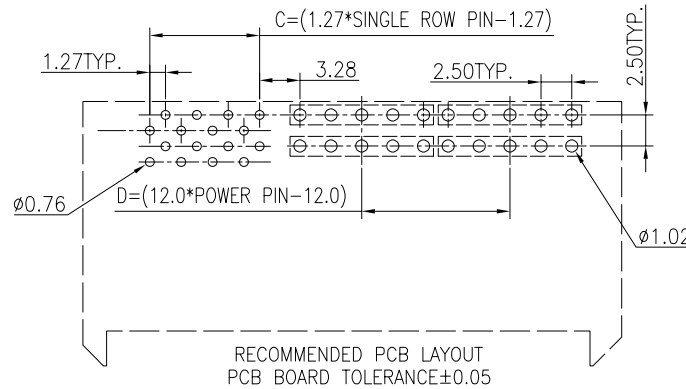
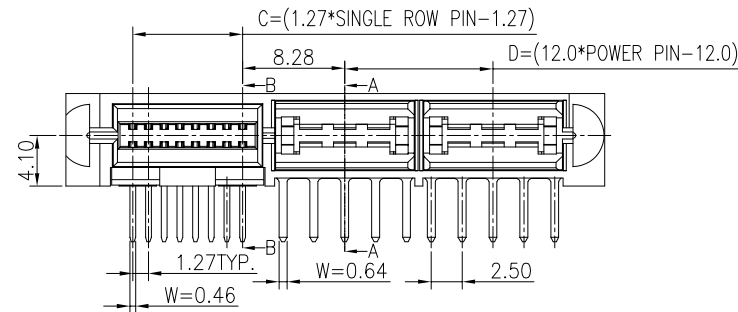
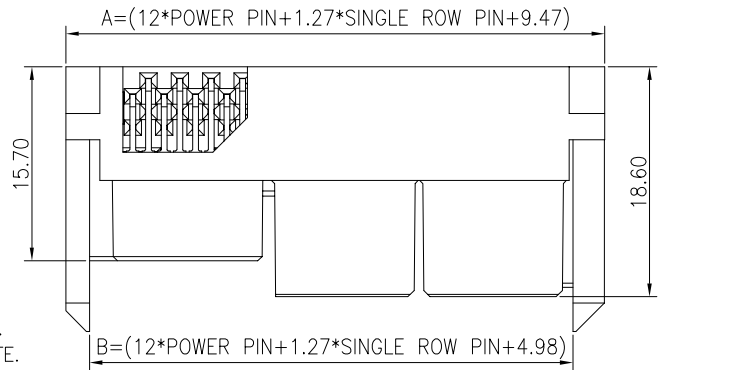
NOTES:

- FINISH:
 - HOUSING: LCP,UL94V-0,BLACK
 - COVER: LCP,UL94V-0,BLACK
 - CONTACT: COPPER ALLOY,
PLATED IN CONTACT AERA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA
- ELECTRICAL:
 - CURRENT RATING: SIGNAL PIN 1.0A.
POWER PIN 30A.
 - DIELECTRIC WITHSTANDING VOLTAGE: SIGNAL PIN 500V DC/MINUTE.
POWER PIN 1000V DC/MINUTE.
 - CONTACT RESISTANCE: SIGNAL PIN 45mΩ MAX.AT DC 20mA.
POWER PIN 2mΩ MAX.AT DC 20mA.
 - INSULATION RESISTANCE: SIGNAL PIN 500V DC/1000MΩ MIN
POWER PIN 500V DC/5000MΩ MIN
- SALT SPRAY TEST:
 - CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST
- MAX PROCESSING TEMP:265°C SECONDS 10S
- OPERATION TEMPERATURE:-40°C TO +105°C.
- ORDER INFORMATION:

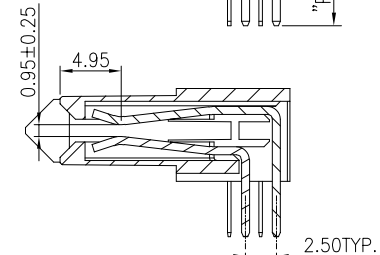
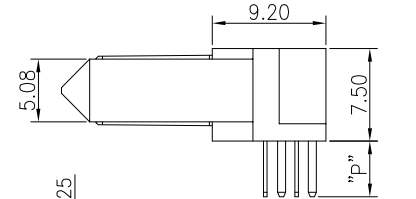
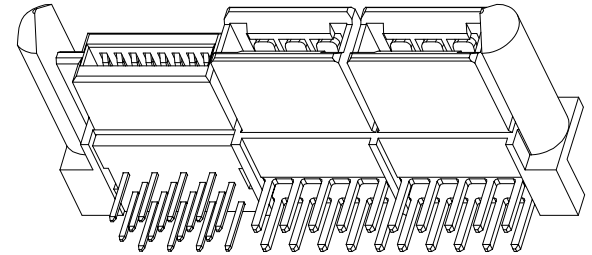
W62F4-F XXX XXX S4 075 C 0X

流水码:	01=2.90 ("P")	02=3.60 ("P")	03=4.50 ("P")
电源Pin数	信号Pin数	端子电镀:	塑胶高度:
002=2*01PIN	012=2*06PIN	S0=Gold Flash/Tin (半金锡)	075=7.50mm
~	~	S1=1u" Gold/Tin	
012=2*06PIN	040=2*20PIN	S2=3u" Gold/Tin	
V		S3=5u" Gold/Tin	
		S4=10u" Gold/Tin	
		S5=15u" Gold/Tin	
		S6=30u" Gold/Tin	

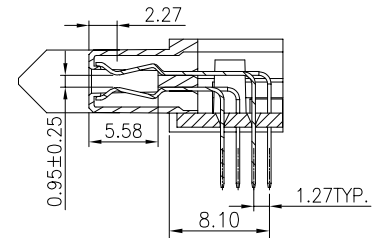
流水码	"P" 焊脚长度	PCB 厚度
01	2.90	1.57
02	3.60	2.36
03	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05



SECTION A-A



SECTION B-B

					OPERATION	DRAW	Mr.Zeng	2025.03.17	SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					X.X ±0.40	DESIGN	Jensen	2025.03.17				
					X.XX ±0.25	CHECK	Jack	2025.03.17				
					X.XXX ±0.15	APPROVE	Andy	2025.03.17				
A0			NEW		Angle ±3°				SIZE	A4	PART NO.	W62F4-F XXX XXX S4 075 C 0X
REV	DATE		MODIFICATION DESCRIPTION	CHANGE	DIM.	TOL	UNIT	mm	SHEET	1/1	TITLE:	母座 电源+信号连接器 卧式90° DIP 带导柱 无定位柱
								SCALE	PROJ.	1:1	DRAW NO.	SP-1471

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: 1.0A./PIN
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: 45mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: 500V DC/1000MΩ MIN

3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.MAX PROCESSING TEMP:265°C SECONDS 10S
- 5.OPERATION TEMPERATURE:-40°C TO +105°C.

6.ORDER INFORMATION:

62F4-F XXX S4 075 C 1X

信号Pin数

端子电镀:

塑胶高度:

流水码:

012=2*06PIN

S0=Gold Flash/Tin

075=7.50mm

11=2.90 ("P")

~

(半金锡)

12=3.60 ("P")

040=2*20PIN

S1=1u" Gold/Tin

S2=3u" Gold/Tin

S3=5u" Gold/Tin

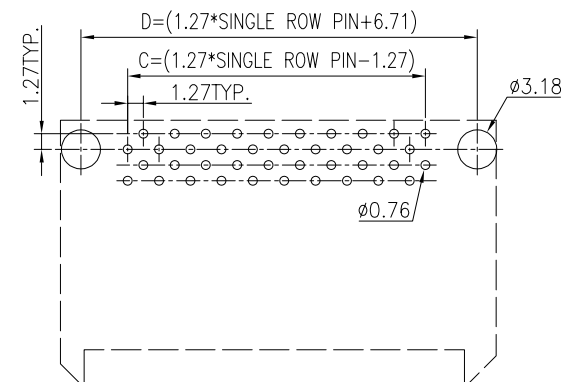
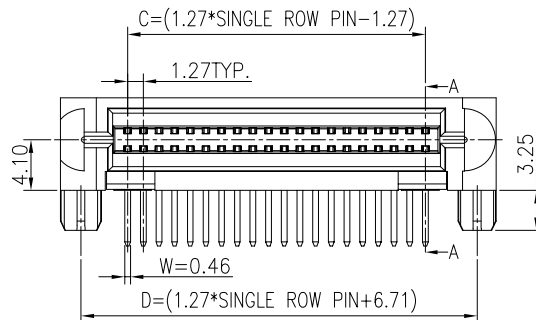
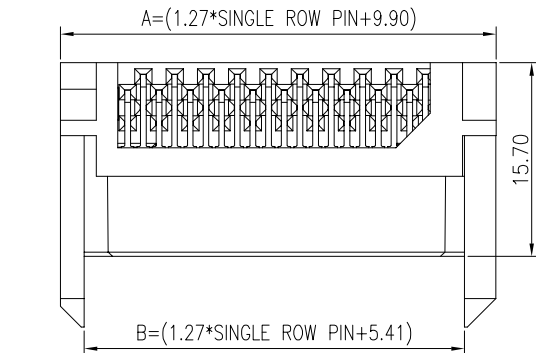
S4=10u" Gold/Tin

S5=15u" Gold/Tin

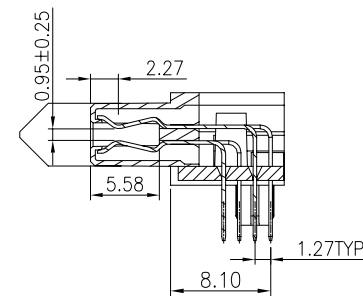
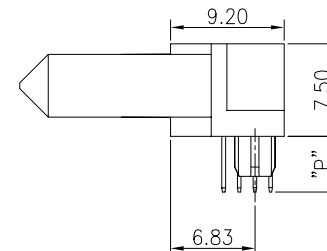
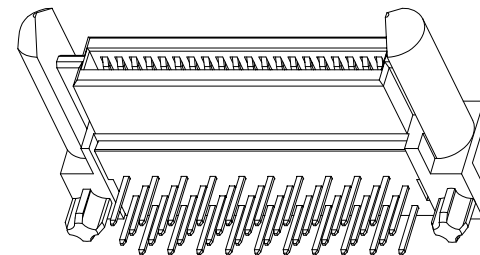
S6=30u" Gold/Tin

13=4.50 ("P")

流水码	"P" 焊脚长度	PCB 厚度
11	2.90	1.57
12	3.60	2.36
13	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE ±0.05



SECTION A-A

					OPERATION	DRAW	Mr.Zeng	2025.03.17	SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					X.X ±0.40	DESIGN	Jensen	2025.03.17				
					X.XX ±0.25	CHECK	Jack	2025.03.17				
					X.XXX ±0.15	APPROVE	Andy	2025.03.17				
A0		NEW			Angle ±3°				SHEET	1/1	TITLE:	母座 信号连接器 卧式90° DIP 带导柱 带定位柱
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM. TOL	UNIT	mm	SCALE	1:1	PROJ.	DRAW NO.	SP-1478

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: 1.0A./PIN
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: 45mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: 500V DC/1000MΩ MIN

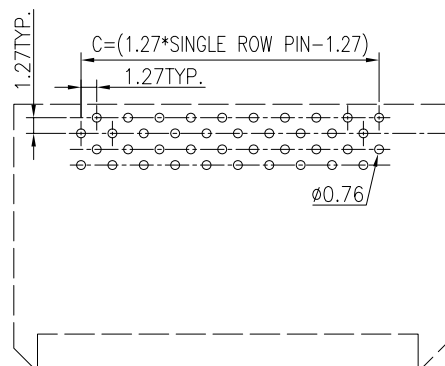
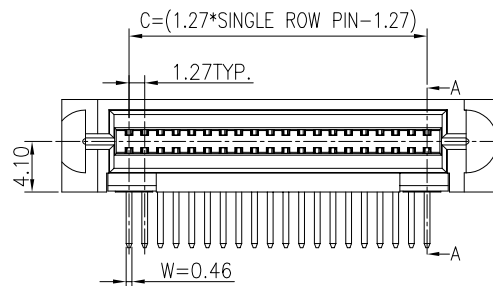
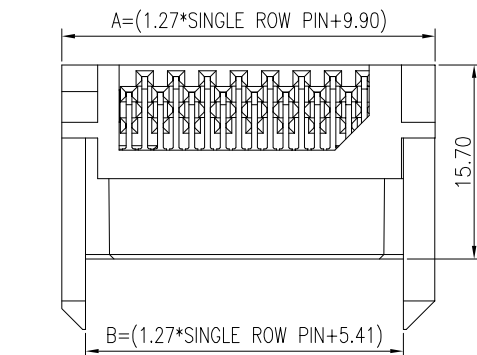
3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.MAX PROCESSING TEMP:265°C SECONDS 10S
- 5.OPERATION TEMPERATURE:-40°C TO +105°C.
- 6.ORDER INFORMATION:

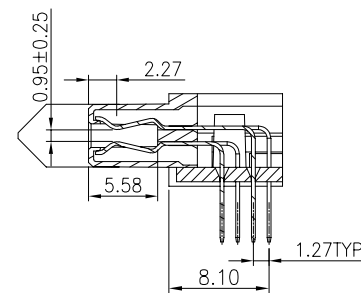
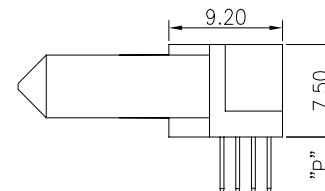
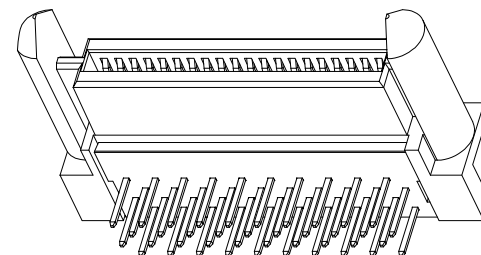
W62F4-F XXX S4 075 C 1X

流水码:	信号Pin数	端子电镀:	塑胶高度:
11=2.90 ("P")	012=2*06PIN	S0=Gold Flash/Tin	075=7.50mm
12=3.60 ("P")	~	(半金锡)	
13=4.50 ("P")	040=2*20PIN	S1=1u" Gold/Tin	
		S2=3u" Gold/Tin	
		S3=5u" Gold/Tin	
		S4=10u" Gold/Tin	
		S5=15u" Gold/Tin	
		S6=30u" Gold/Tin	

流水码	"P" 焊脚长度	PCB 厚度
11	2.90	1.57
12	3.60	2.36
13	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE ±0.05



SECTION A-A

					OPERATION	DRAW	Mr.Zeng	2025.03.17	SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					X.X ±0.40	DESIGN	Jensen	2025.03.17				
					X.XX ±0.25	CHECK	Jack	2025.03.17				
					X.XXX ±0.15	APPROVE	Andy	2025.03.17				
A0			NEW		Angle ±3°				SHEET	1/1	TITLE:	母座 信号连接器 卧式90° DIP 带导柱 无定位柱
REV	DATE		MODIFICATION DESCRIPTION	CHANGE	DIM. TOL	UNIT	mm	SCALE	1:1	PROJ.	DRAW NO.	SP-1479

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: 30A.
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 1000V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: 2mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: 500V DC/5000MΩ MIN

3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST

4.MAX PROCESSING TEMP:265°C SECONDS 10S

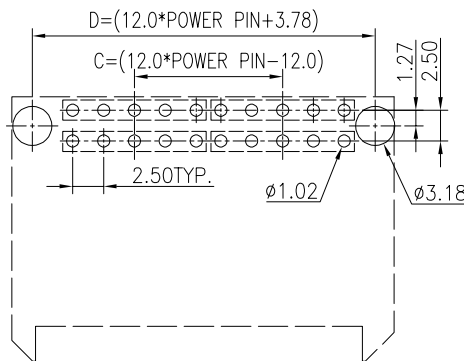
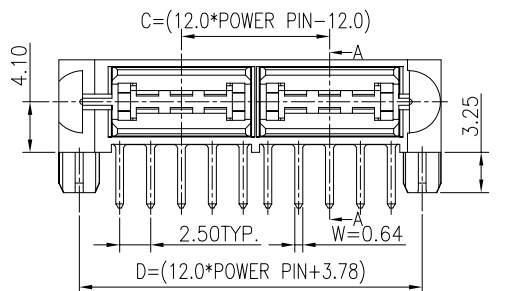
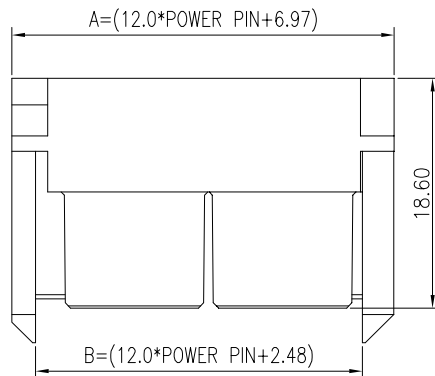
5.OPERATION TEMPERATURE:-40°C TO +105°C.

6.ORDER INFORMATION:

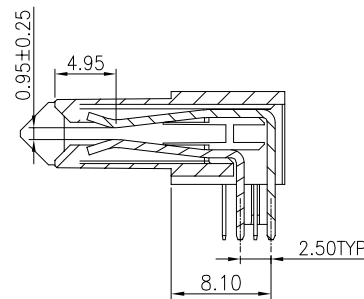
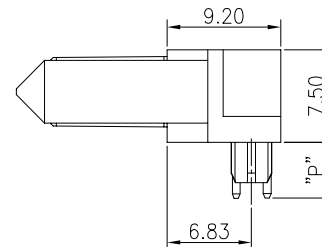
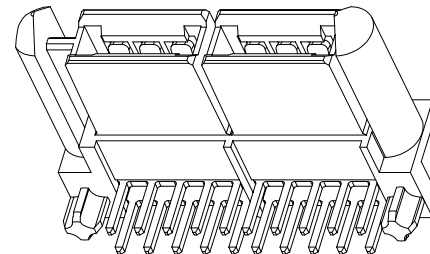
62F4-F XXX S4 075 C 2X

流水码:	21=2.90 ("P")
端子电镀:	22=3.60 ("P")
塑胶高度:	23=4.50 ("P")
电源Pin数	
002=2*01PIN	S0=Gold Flash/Tin (半金锡)
~	
012=2*06PIN	S1=1u" Gold/Tin
	S2=3u" Gold/Tin
	S3=5u" Gold/Tin
	S4=10u" Gold/Tin
	S5=15u" Gold/Tin
	S6=30u" Gold/Tin

流水码	"P" 焊脚长度	PCB 厚度
21	2.90	1.57
22	3.60	2.36
23	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05



SECTION A-A

OPERATION

DRAW

Mr.Zeng

2025.03.17

X.X ±0.40

DESIGN

Jensen

2025.03.17

X.XX ±0.25

CHECK

Jack

2025.03.17

X.XXX ±0.15

APPROVE

Andy

2025.03.17

Angle ±3°

UNIT

mm

SCALE

1:1

DIM. TOL

PROJ.

DRAW NO.

SP-1485

SOLEPIN 东莞市硕品电子有限公司
PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE A4 PART NO. 62F4-F XXX S4 075 C 2X

SHEET 1/1 TITLE: 电源连接器 母座 卧式90° 带导柱 带定位柱

REV DATE MODIFICATION DESCRIPTION CHANGE APPROVE

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: 30A.
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 1000V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: 2mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: 500V DC/5000MΩ MIN

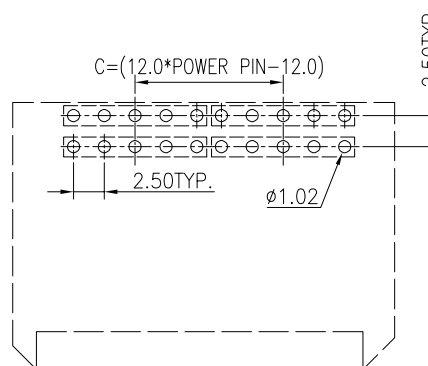
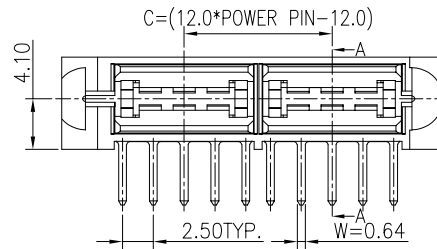
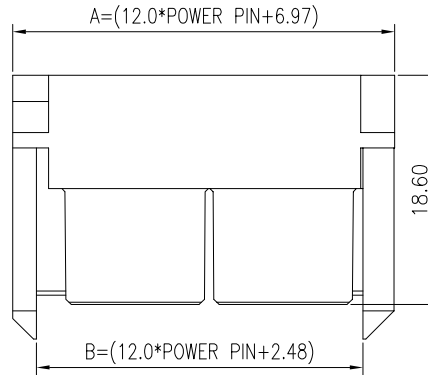
3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.MAX PROCESSING TEMP:265°C SECONDS 10S
- 5.OPERATION TEMPERATURE:-40°C TO +105°C.
- 6.ORDER INFORMATION:

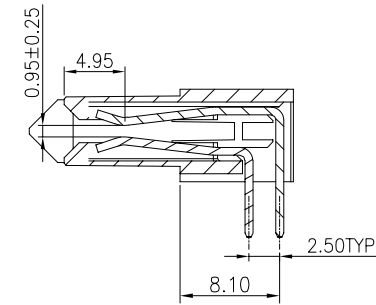
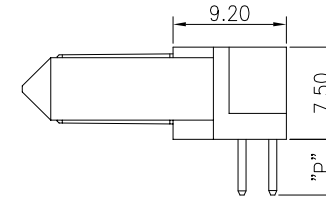
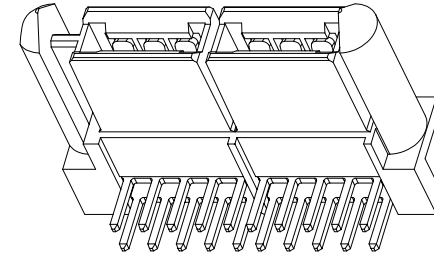
W62F4-F XXX S4 075 C 2X

电源Pin数	端子电镀:	塑胶高度:	流水码:
002=2*01PIN	S0=Gold Flash/Tin	075=7.50mm	21=2.90("P")
~	(半金锡)		22=3.60("P")
012=2*06PIN	S1=1u" Gold/Tin		23=4.50("P")
	S2=3u" Gold/Tin		
	S3=5u" Gold/Tin		
	S4=10u" Gold/Tin		
	S5=15u" Gold/Tin		
	S6=30u" Gold/Tin		

流水码	"P" 焊脚长度	PCB 厚度
21	2.90	1.57
22	3.60	2.36
23	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05



SECTION A-A

					OPERATION		DRAW		Mr.Zeng		2025.03.17		SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.				
					X.X	±0.40	DESIGN		Jensen		2025.03.17						
					X.XX	±0.25	CHECK		Jack		2025.03.17						
					X.XXX	±0.15	APPROVE		Andy		2025.03.17						
A0		NEW		——	——	Angle	±3°	APPROVE		Andy		2025.03.17		SHEET	1/1	TITLE:	电源连接器 母座 卧式90° 带导柱 无定位柱
REV	DATE	MODIFICATION DESCRIPTION		CHANGE	APPROVE	DIM.	TOL	UNIT		mm	SCALE	1:1	PROJ.		DRAW NO.	SP-1486	

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: SIGNAL PIN 1.0A.
POWER PIN 30A.
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: SIGNAL PIN 500V DC/MINUTE.
POWER PIN 1000V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: SIGNAL PIN 45mΩ MAX.AT DC 20mA.
POWER PIN 2mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: SIGNAL PIN 500V DC/1000MΩ MIN
POWER PIN 500V DC/5000MΩ MIN

3.SALT SPRAY TEST:

3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST

4.MAX PROCESSING TEMP:265°C SECONDS 10S

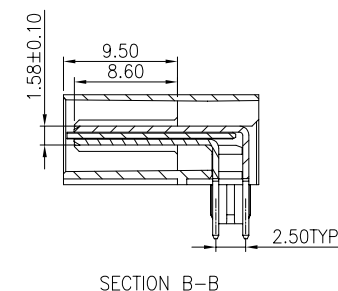
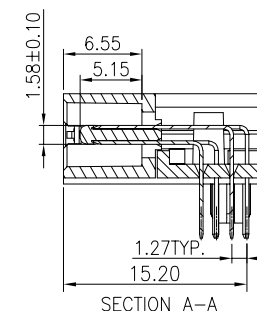
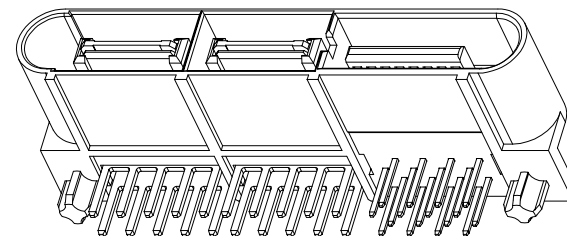
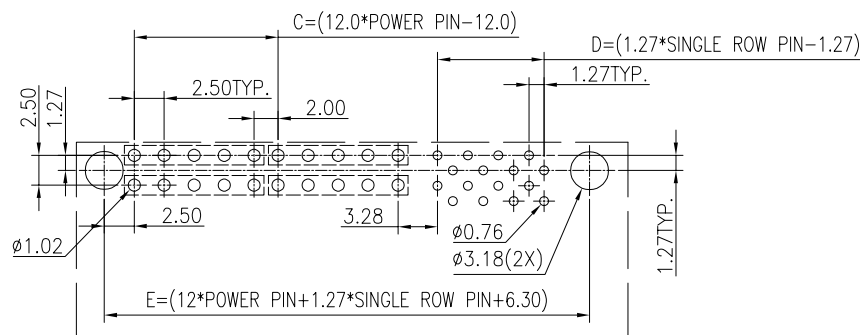
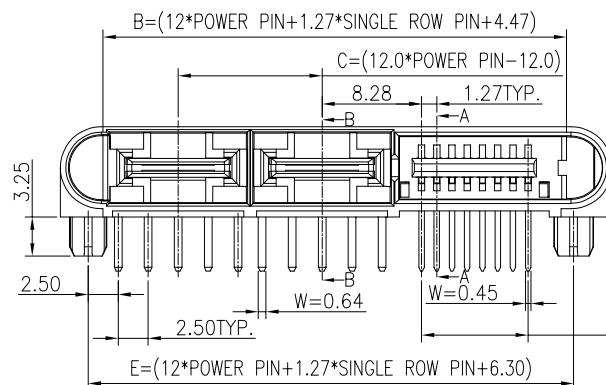
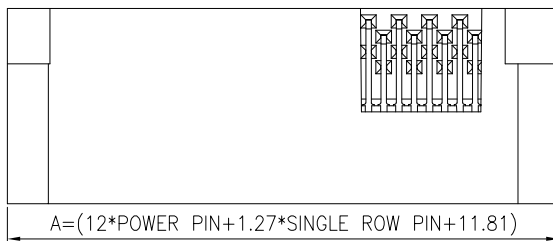
5.OPERATION TEMPERATURE:-40°C TO +105°C.

6.ORDER INFORMATION:

62F4-M XXX XXX S4 075 C 0X

流水码: 01=2.90("P")
02=3.60("P")
03=4.50("P")
电源Pin数 信号Pin数 端子电镀: 塑胶高度: 02=2*01PIN 012=2*06PIN S0=Gold Flash/Tin 075=7.52mm (半金锡)
012=2*06PIN 040=2*20PIN S1=1u" Gold/Tin
S2=3u" Gold/Tin
S3=5u" Gold/Tin
S4=10u" Gold/Tin
S5=15u" Gold/Tin
S6=30u" Gold/Tin

流水码	"P" 焊脚长度	PCB 厚度
01	2.90	1.57
02	3.60	2.36
03	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05

					OPERATION	DRAW	Mr.Zeng	2025.03.17	SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					X.X ±0.40	DESIGN	Jensen	2025.03.17	SIZE	A4	PART NO.	62F4-M XXX XXX S4 075 C 0X
					X.XX ±0.25	CHECK	Jack	2021.09.23	SHEET	1/1	TITLE:	公头 电源+信号连接器 卧式90° DIP 带导柱 带定位柱
					X.XXX ±0.15	APPROVE	Andy	2025.03.17	PROJ.	Φ	DRAW NO.	SP-1467
AO	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	Angle ±3°	UNIT	mm	SCALE	1:1			
REV					DIM. TOL							

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: SIGNAL PIN 1.0A.
POWER PIN 30A.
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: SIGNAL PIN 500V DC/MINUTE.
POWER PIN 1000V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: SIGNAL PIN 45mΩ MAX.AT DC 20mA.
POWER PIN 2mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: SIGNAL PIN 500V DC/1000MΩ MIN
POWER PIN 500V DC/5000MΩ MIN

3.SALT SPRAY TEST:

3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST

4.MAX PROCESSING TEMP:265°C SECONDS 10S

5.OPERATION TEMPERATURE:-40°C TO +105°C.

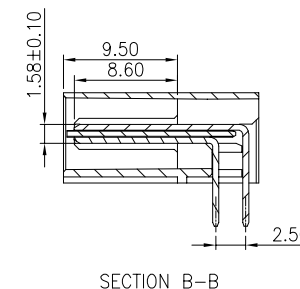
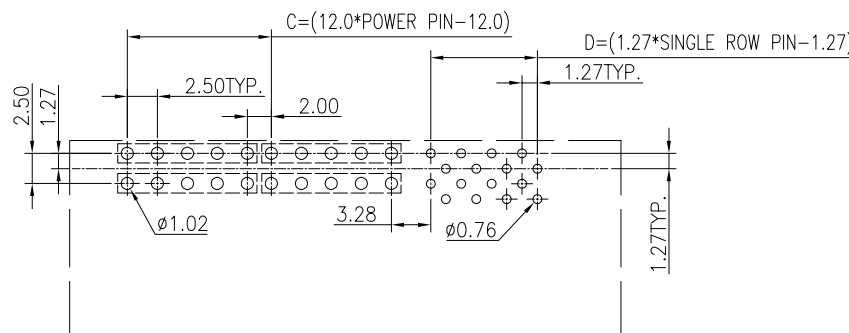
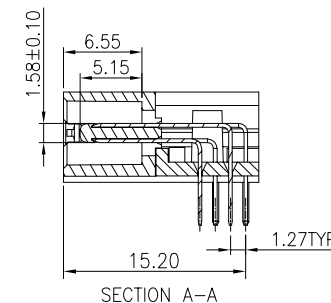
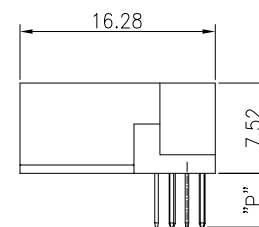
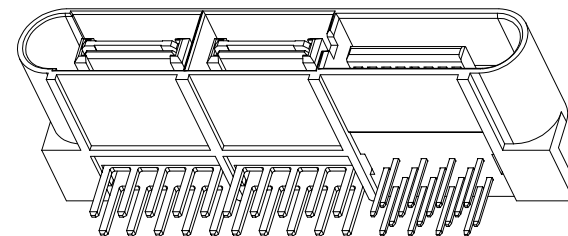
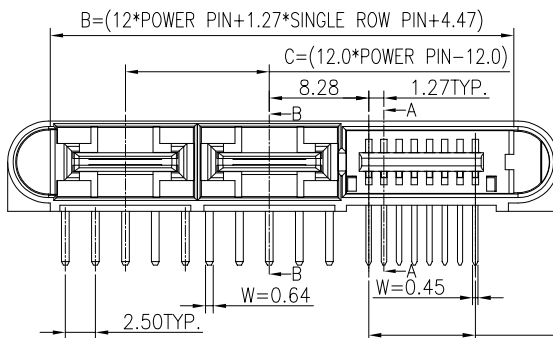
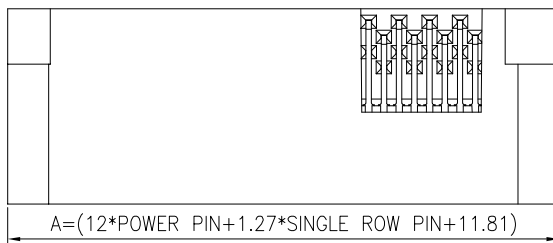
6.ORDER INFORMATION:

W62F4-M XXX XXX S4 075 C OX

流水码: 01=2.90 ("P")
02=2*01PIN 012=2*06PIN S0=Gold Flash/Tin 075=7.52mm 03=4.50 ("P")
~ (半金锡)

012=2*06PIN 040=2*20PIN
S1=1u" Gold/Tin
S2=3u" Gold/Tin
S3=5u" Gold/Tin
S4=10u" Gold/Tin
S5=15u" Gold/Tin
S6=30u" Gold/Tin

流水码	"P" 焊脚长度	PCB 厚度
01	2.90	1.57
02	3.60	2.36
03	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05

					OPERATION		DRAW		Mr.Zeng		2025.03.17		SOLEPiN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.							
					X.X	±0.40	DESIGN		Jensen		2025.03.17									
					X.XX	±0.25	CHECK		Jack		2025.03.17						SIZE	A4	PART NO.	W62F4-M XXX XXX S4 075 C 0X
					X.XXX	±0.15	APPROVE		Andy		2025.03.17						SHEET	1/1	TITLE:	公头 电源+信号连接器 卧式90° DIP 带导柱 无定位柱
A0		NEW		————	————	Angle	±3°													
REV	DATE	MODIFICATION DESCRIPTION		CHANGE	APPROVE	DIM.	TOL	UNIT		mm	SCALE	1:1	PROJ.		DRAW NO.	SP-1466				

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AERA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: 1.0A./PIN
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: 45mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: 500V DC/1000MΩ MIN

3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATUREIS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.MAX PROCESSING TEMP:265°C SECONDS 10S
- 5.OPERATION TEMPERATURE:-40°C TO +105°C.
- 6.ORDER INFORMATION:

62F4-M XXX S4 075 C 1X

信号Pin数
012=2*06PIN
~
040=2*20PIN

端子电镀:
S0=Gold Flash/Tin
(半金锡)
S1=1u" Gold/Tin
S2=3u" Gold/Tin
S3=5u" Gold/Tin
S4=10u" Gold/Tin
S5=15u" Gold/Tin
S6=30u" Gold/Tin

塑胶高度: 075=7.52mm
13=4.50("P")

流水码:
11=2.90("P")
12=3.60("P")

流水码	"P" 焊脚长度	PCB 厚度
11	2.90	1.57
12	3.60	2.36
13	4.50	3.18

RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05

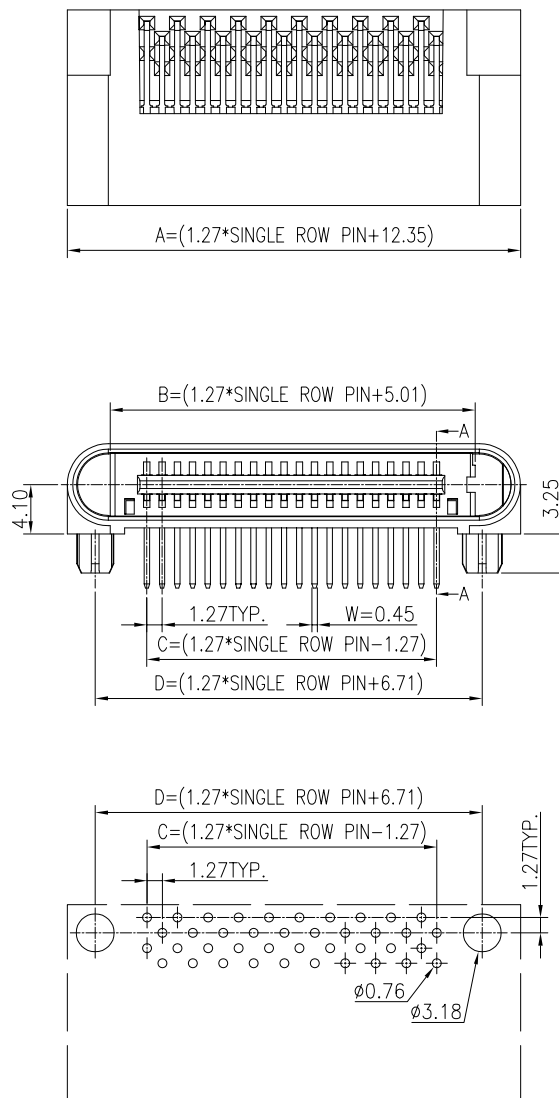
					OPERATION	DRAW	Mr.Zeng	2025.03.17	SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					X.X ±0.40	DESIGN	Jensen	2025.03.17				
					X.XX ±0.25	CHECK	Jack	2025.03.17				
					X.XXX ±0.15	APPROVE	Andy	2025.03.17				
A0		NEW			Angle ±3°				SHEET	1/1	TITLE:	公头 信号连接器 90° DIP 带导柱 带定位柱
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM. TOL	UNIT	mm	SCALE	1:1	PROJ.	DRAW NO.	SP-1475

- 1.FINISH:
 - 1.1 HOUSING: LCP,UL94V-0,BLACK
 - 1.2 COVER: LCP,UL94V-0,BLACK
 - 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA
2. ELECTRICAL:
 - 2.1 CURRENT RATING: 1.0A./PIN
 - 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V DC/MINUTE.
 - 2.3 CONTACT RESISTANCE: 45mΩ MAX.AT DC 20mA.
 - 2.4 INSULATION RESISTANCE: 500V DC/1000MΩ MIN
- 3.SALT SPRAY TEST:
 - 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST
 - 4.MAX PROCESSING TEMP:265°C SECONDS 10S
 - 5.OPERATION TEMPERATURE:-40°C TO +105°C.
 - 6.ORDER INFORMATION:

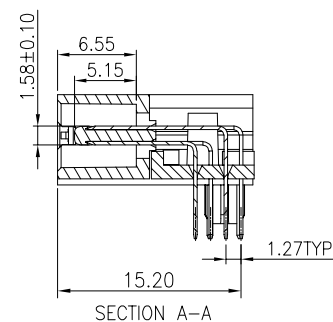
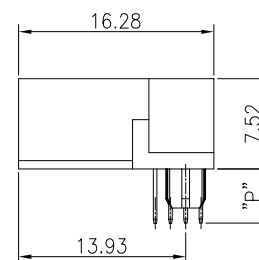
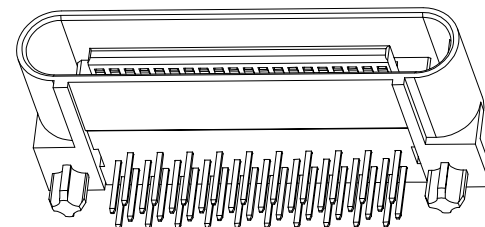
62F4-M XXX S4 075 C 1X

Pin数 端子电镀: 塑胶高度: 流水码:
2*06PIN S0=Gold Flash/Tin 075=7.52mm 11=2.90("P")
(半金锡) 12=3.60("P")
2*20PIN S1=1u" Gold/Tin 13=4.50("P")
S2=3u" Gold/Tin
S3=5u" Gold/Tin
S4=10u" Gold/Tin
S5=15u" Gold/Tin
S6=30u" Gold/Tin

流水码	"P" 焊脚长度	PCB 厚度
11	2.90	1.57
12	3.60	2.36
13	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE ± 0.05



					OPERATION		DRAW		Mr.Zeng		2025.03.17		SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.					
					X.X	±0.40	DESIGN		Jensen		2025.03.17							
					X.XX	±0.25	CHECK		Jack		2025.03.17		SIZE	A4	PART NO.	62F4-M XXX S4 075 C 1X		
A0		NEW			X.XXX	±0.15	APPROVE		Andy		2025.03.17		SHEET	1/1	TITLE:	公头 信号连接器 90° DIP 带导柱 带定位柱		
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	Angle	±3°												
					DIM.	TOL	UNIT		mm		SCALE		1:1		PROJ.		DRAW NO.	SP-1475

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: 1.0A./PIN
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: 45mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: 500V DC/1000MΩ MIN

3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS $35\pm 2^{\circ}\text{C}$,
TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.MAX PROCESSING TEMP:265°C SECONDS 10S
- 5.OPERATION TEMPERATURE:-40°C TO +105°C.
- 6.ORDER INFORMATION:

W62F4-M XXX S4 075 C 1X

信号Pin数

012=2*06PIN

~

040=2*20PIN

端子电镀:

S0=Gold Flash/Tin

(半金锡)

S1=1u" Gold/Tin

S2=3u" Gold/Tin

S3=5u" Gold/Tin

S4=10u" Gold/Tin

S5=15u" Gold/Tin

S6=30u" Gold/Tin

塑胶高度:

075=7.52mm

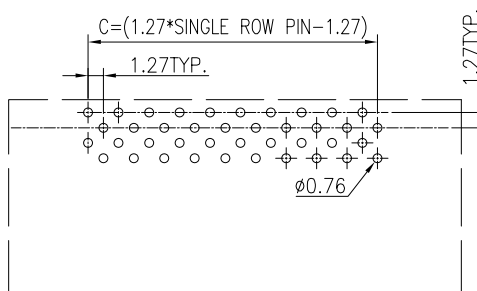
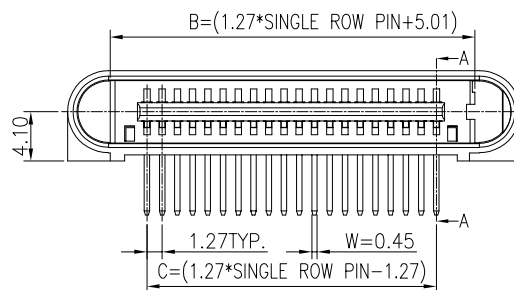
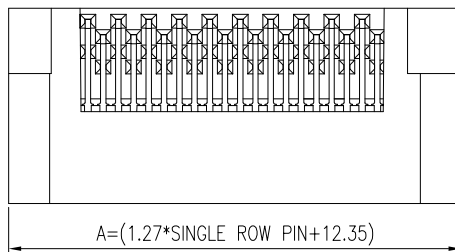
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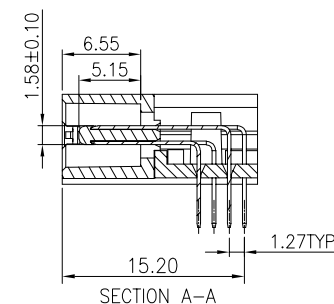
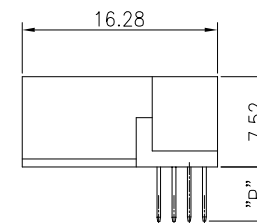
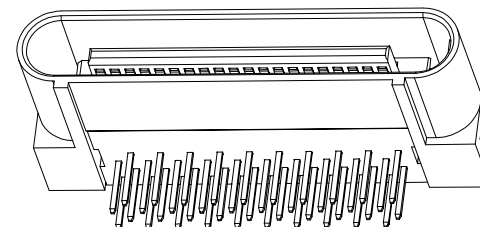
12=3.60("P")

13=4.50("P")

流水码	"P" 焊脚长度	PCB 厚度
11	2.90	1.57
12	3.60	2.36
13	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE ± 0.05



OPERATION

X.X ±0.40

X.XX ±0.25

X.XXX ±0.15

Angle ±3°

DIM. TOL

DRAW

DESIGN

CHECK

APPROVE

UNIT

Mr.Zeng

Jensen

Jack

Andy

mm

2025.03.17

2025.03.17

2025.03.17

2025.03.17

SCALE

1:1

SOLEPIN 东莞市硕品电子有限公司
PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE A4 PART NO. W62F4-M XXX S4 075 C 1X

SHEET 1/1 TITLE: 公头 信号连接器 90° DIP 带导柱 无定位柱

PROJ. DRAW NO. SP-1474

A0

REV

1 2 3 4 5 6 7 8 9 10

客户图

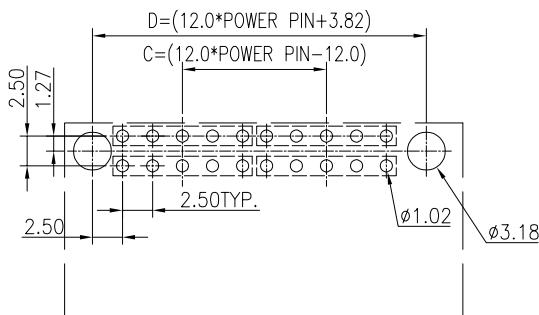
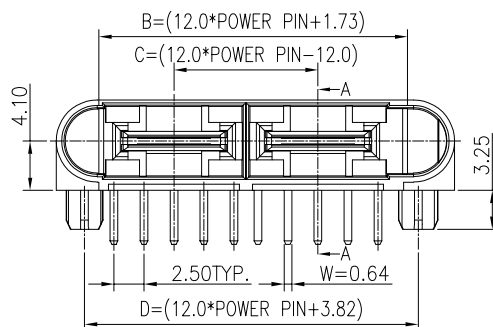
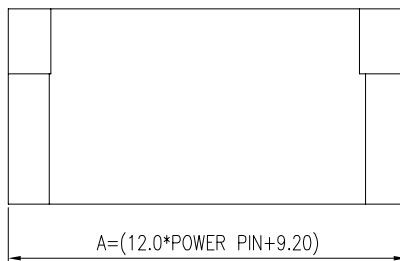
NOTES:

- 1.FINISH:
 - 1.1 HOUSING: LCP,UL94V-0,BLACK
 - 1.2 COVER: LCP,UL94V-0,BLACK
 - 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA
2. ELECTRICAL:
 - 2.1 CURRENT RATING: 30A.
 - 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 1000V DC/MINUTE.
 - 2.3 CONTACT RESISTANCE: 2mΩ MAX.AT DC 20mA.
 - 2.4 INSULATION RESISTANCE: 500V DC/5000MΩ MIN
- 3.SALT SPRAY TEST:
 - 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.MAX PROCESSING TEMP:265°C SECONDS 10S
- 5.OPERATION TEMPERATURE:-40°C TO +105°C.
- 6.ORDER INFORMATION:

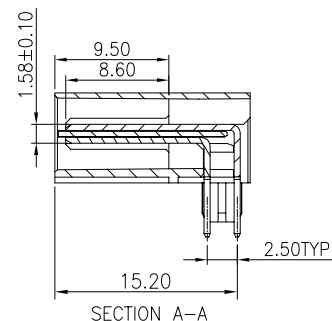
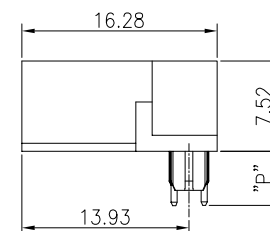
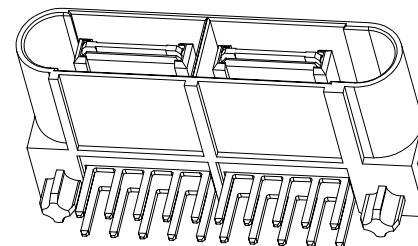
62F4-M XXX S4 075 C 2X

电源Pin数	端子电镀:	塑胶高度:	流水码:
002=2*01PIN	S0=Gold Flash/Tin	075=7.52mm	21=2.90("P")
~	(半金锡)		22=3.60("P")
012=2*06PIN	S1=1u" Gold/Tin		23=4.50("P")
	S2=3u" Gold/Tin		
	S3=5u" Gold/Tin		
	S4=10u" Gold/Tin		
	S5=15u" Gold/Tin		
	S6=30u" Gold/Tin		

流水码	"P" 焊脚长度	PCB 厚度
21	2.90	1.57
22	3.60	2.36
23	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05



					OPERATION		DRAW		Mr.Zeng		2025.03.17		SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					X.X	±0.40	DESIGN		Jensen		2025.03.17					
					X.XX	±0.25	CHECK		Jack		2025.03.17		SIZE	A4	PART NO.	62F4-M XXX S4 075 C 2X
A0		NEW			X.XXX	±0.15	APPROVE		Andy		2025.03.17		SHEET	1/1	TITLE:	公头 电源连接器 90° 带导柱 带定位柱
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	Angle	±3°										
					DIM.	TOL	UNIT		mm	SCALE	1:1	PROJ.		DRAW NO.	SP-1482	

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: 30A.
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 1000V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: 2mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: 500V DC/5000MΩ MIN

3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST

4.MAX PROCESSING TEMP:265°C SECONDS 10S

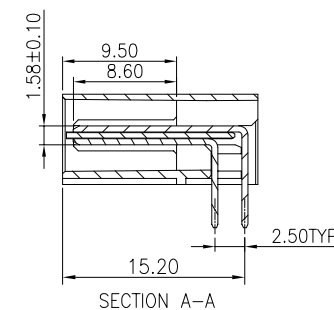
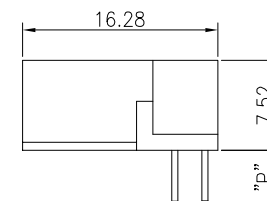
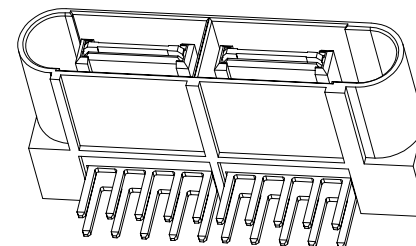
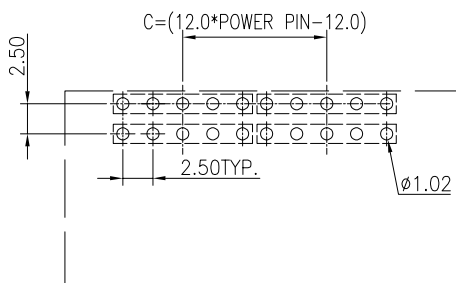
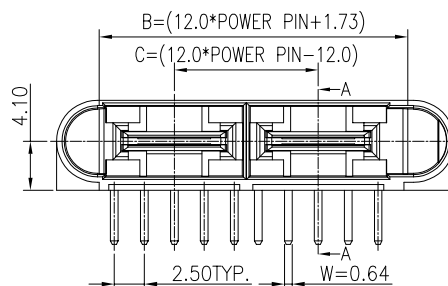
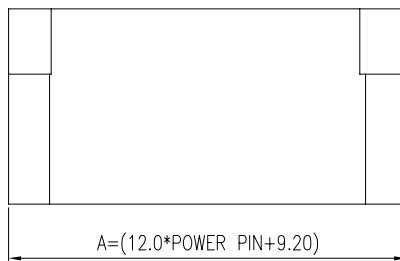
5.OPERATION TEMPERATURE:-40°C TO +105°C.

6.ORDER INFORMATION:

W62F4-M XXX S4 075 C 2X

		流水码:	
电源Pin数	端子电镀:	塑胶高度:	21=2.90("P")
002=2*01PIN	S0=Gold Flash/Tin	075=7.52mm	22=3.60("P")
~	(半金锡)		23=4.50("P")
012=2*06PIN	S1=1u" Gold/Tin		
	S2=3u" Gold/Tin		
	S3=5u" Gold/Tin		
	S4=10u" Gold/Tin		
	S5=15u" Gold/Tin		
	S6=30u" Gold/Tin		

流水码	"p" 焊脚长度	PCB 厚度
21	2.90	1.57
22	3.60	2.36
23	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05

					OPERATION	DRAW	Mr.Zeng	2025.03.17	SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					X.X ±0.40	DESIGN	Jensen	2025.03.17				
					X.XX ±0.25	CHECK	Jack	2025.03.17				
					X.XXX ±0.15	APPROVE	Andy	2025.03.17				
AO		NEW			Angle ±3°				SHEET	1/1	TITLE:	公头 电源连接器 90° 带导柱无定位柱
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM. TOL	UNIT	mm	SCALE	1:1	PROJ.	DRAW NO.	SP-1481

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: SIGNAL PIN 1.0A.
POWER PIN 30A.
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: SIGNAL PIN 500V DC/MINUTE.
POWER PIN 1000V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: SIGNAL PIN 45mΩ MAX.AT DC 20mA.
POWER PIN 2mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: SIGNAL PIN 500V DC/1000MΩ MIN
POWER PIN 500V DC/5000MΩ MIN

3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST

4.MAX PROCESSING TEMP:265°C SECONDS 10S

5.OPERATION TEMPERATURE:-40°C TO +105°C.

6.ORDER INFORMATION:

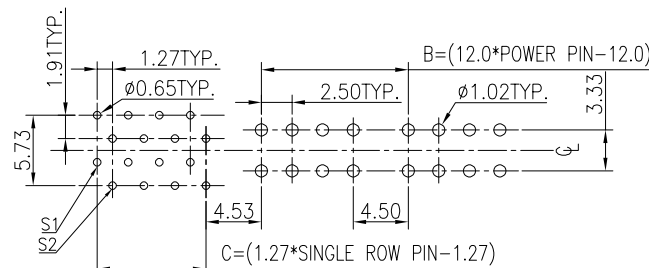
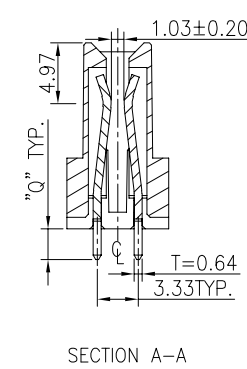
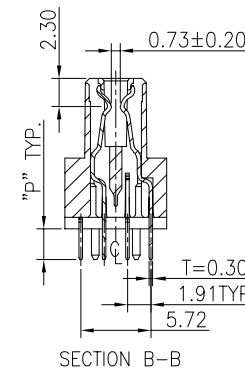
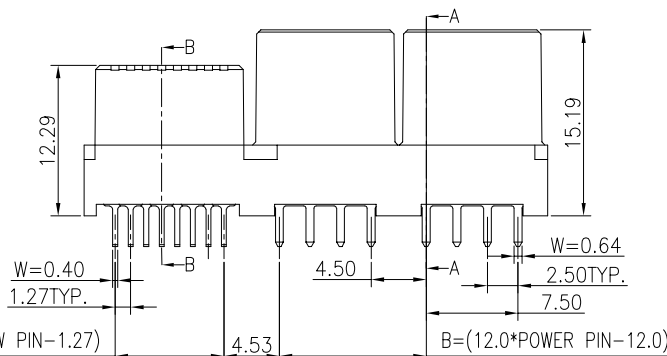
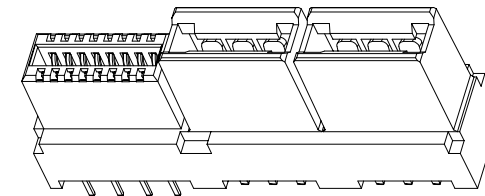
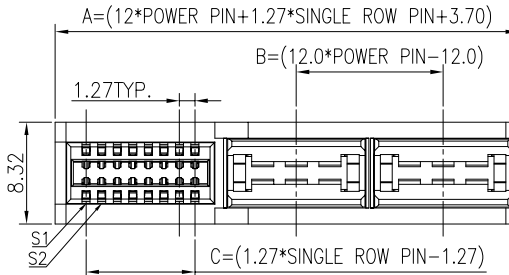
62F5V-F XXX XXX S4 151 C 0X

流水码: 01=("/Q")
02=("/Q")
03=("/Q")

电源Pin数 信号Pin数 端子电镀: 塑胶高度: 02=("/Q")
002=2*01PIN 012=2*06PIN S0=Gold Flash/Tin 151=15.19mm 03=("/Q")
~ ~ ~ (半金锡)

012=2*06PIN 040=2*20PIN S1=1u" Gold/Tin
S2=3u" Gold/Tin
S3=5u" Gold/Tin
S4=10u" Gold/Tin
S5=15u" Gold/Tin
S6=30u" Gold/Tin

流水码	"P" 信号焊脚长度	"Q" 电源焊脚长度
01	2.35	2.31
02	2.58	2.51
03	3.13	3.06



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05

OPERATION		DRAW		Mr.Zeng		2025.03.17	
X.X	±0.40	DESIGN	Jensen	2025.03.17			
X.XX	±0.25	CHECK	Jack	2025.03.17			
X.XXX	±0.15	APPROVE	Andy	2025.03.17			
Angle	±3°						
DIM.	TOL	UNIT	mm	SCALE	1:1		

SOLEPIN 东莞市硕品电子有限公司
PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

REV		DATE		MODIFICATION DESCRIPTION		CHANGE		APPROVE	
A0				NEW					

SIZE	A4	PART NO.	62F5V-F XXX XXX S4 151 C 0X
SHEET	1/1	TITLE:	母座 电源+信号连接器 立式180° DIP 无导柱
PROJ.	☞	DRAW NO.	SP-1493

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AERA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: 1.0A./PIN
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: 45mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: 500V DC/1000MΩ MIN

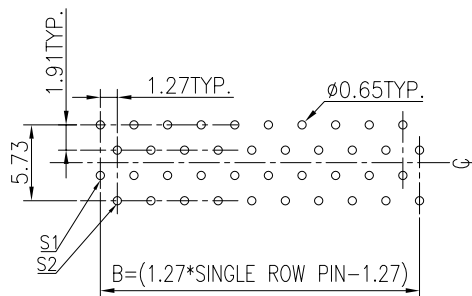
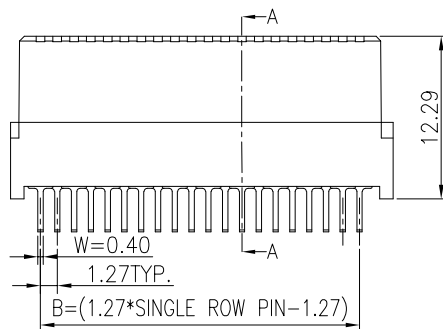
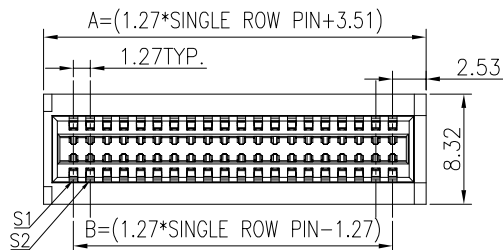
3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.MAX PROCESSING TEMP:265°C SECONDS 10S
- 5.OPERATION TEMPERATURE:-40°C TO +105°C.
- 6.ORDER INFORMATION:

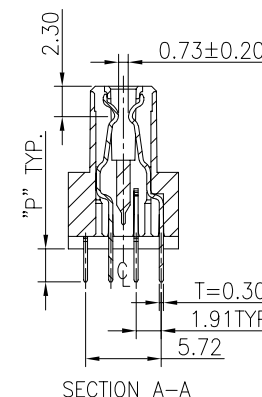
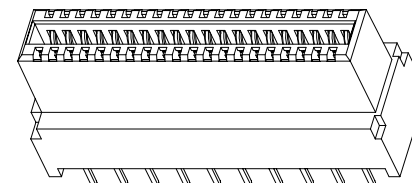
62F5V-F XXX S4 122 C 1X

信号Pin数	端子电镀:	塑胶高度:	流水码:
012=2*06PIN	S0=Gold Flash/Tin	122=12.29mm	11=2.35("P")
~	(半金锡)		12=2.58("P")
040=2*20PIN	S1=1u" Gold/Tin		
	S2=3u" Gold/Tin		
	S3=5u" Gold/Tin		
	S4=10u" Gold/Tin		
	S5=15u" Gold/Tin		
	S6=30u" Gold/Tin		

流水码	"P" 信号焊脚长度
11	2.35
12	2.58
13	3.13



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE ±0.05



OPERATION

X.X ±0.40

X.XX ±0.25

X.XXX ±0.15

Angle ±3°

DIM. TOL

DRAW

DESIGN

CHECK

APPROVE

UNIT

mm

Mr.Zeng

Jensen

Jack

Andy

SCALE

1:1

2025.03.17

2025.03.17

2025.03.17

2025.03.17

SOLEPIN 东莞市硕品电子有限公司
PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE

A4

SHEET

1/1

PROJ.

PROJ.

PART NO.

TITLE:

DRAW NO.

62F5V-F XXX S4 122 C 1X

母座 信号连接器 立式180° DIP 无导柱

SP-1494

A0

REV

1

2

3

4

5

6

7

8

9

10

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: 30A.
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 1000V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: 2mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: 500V DC/5000MΩ MIN

3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST

4.MAX PROCESSING TEMP:265°C SECONDS 10S

5.OPERATION TEMPERATURE:-40°C TO +105°C.

6.ORDER INFORMATION:

62F5V-F XXX S4 151 C 2X

电源Pin数

002=2*01PIN

~

012=2*06PIN

端子电镀:

S0=Gold Flash/Tin

(半金锡)

S1=1u" Gold/Tin

S2=3u" Gold/Tin

S3=5u" Gold/Tin

S4=10u" Gold/Tin

S5=15u" Gold/Tin

S6=30u" Gold/Tin

塑胶高度:

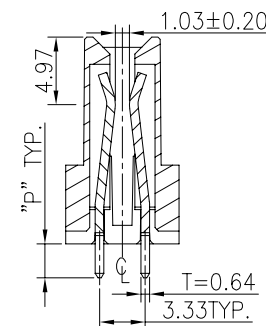
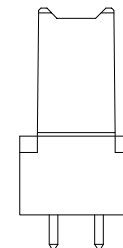
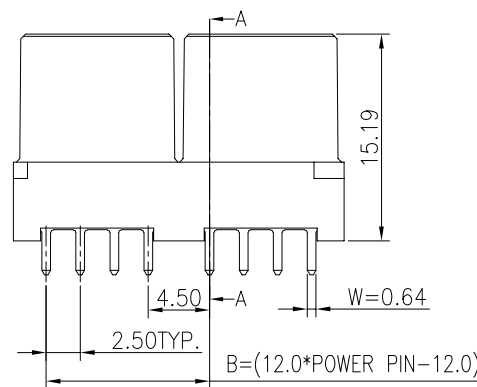
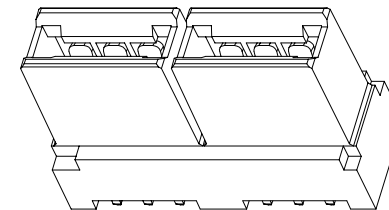
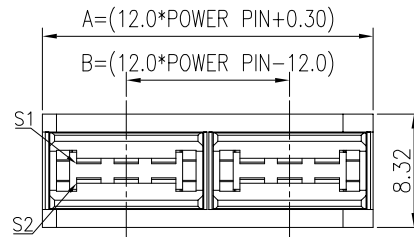
151=15.19mm

流水码:

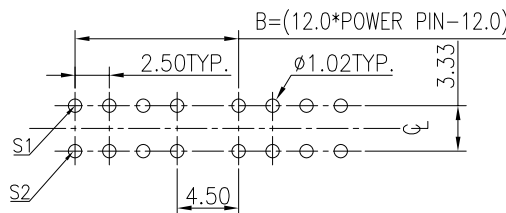
21=2.31("P")

22=2.51("P")

23=3.06("P")



SECTION A-A



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05

流水码	"P" 电源焊脚长度
21	2.31
22	2.51
23	3.06

OPERATION

DRAW

Mr.Zeng

2025.03.17

X.X ±0.40

DESIGN

Jensen

2025.03.17

X.XX ±0.25

CHECK

Jack

2025.03.17

X.XXX ±0.15

APPROVE

Andy

2025.03.17

Angle ±3°

DIM. TOL

UNIT

mm

SCALE

1:1

PROJ.

DRAW NO.

SP-1495

SOLEPIN 东莞市硕品电子有限公司
PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE A4 PART NO. 62F5V-F XXX S4 151 C 2X

SHEET 1/1 TITLE: 母座 电源连接器 立式180° 无导柱

REV DATE MODIFICATION DESCRIPTION CHANGE APPROVE

REV DATE MODIFICATION DESCRIPTION CHANGE APPROVE

REV DATE MODIFICATION DESCRIPTION CHANGE APPROVE

REV DATE MODIFICATION DESCRIPTION CHANGE APPROVE

REV DATE MODIFICATION DESCRIPTION CHANGE APPROVE

REV DATE MODIFICATION DESCRIPTION CHANGE APPROVE

REV DATE MODIFICATION DESCRIPTION CHANGE APPROVE

REV DATE MODIFICATION DESCRIPTION CHANGE APPROVE

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: SIGNAL PIN 1.0A.
POWER PIN 30A.
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: SIGNAL PIN 500V DC/MINUTE.
POWER PIN 1000V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: SIGNAL PIN 45mΩ MAX.AT DC 20mA.
POWER PIN 2mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: SIGNAL PIN 500V DC/1000MΩ MIN
POWER PIN 500V DC/5000MΩ MIN

3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS $35\pm 2^{\circ}\text{C}$,
TEST TIME 8H MIN,NO OXIDATION OR RUST

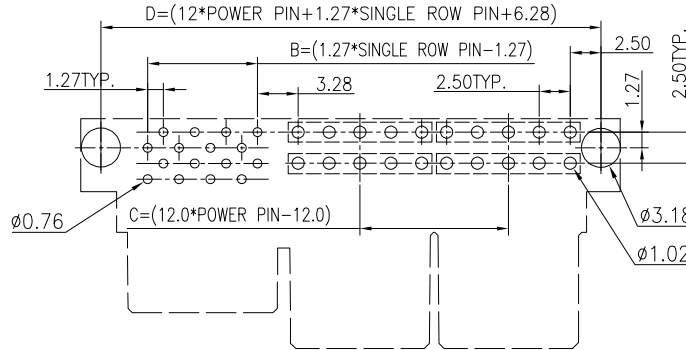
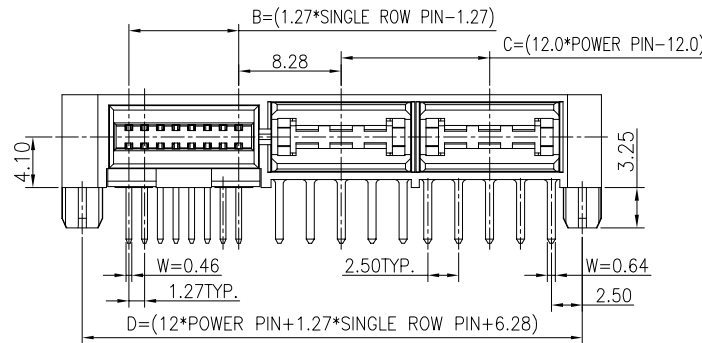
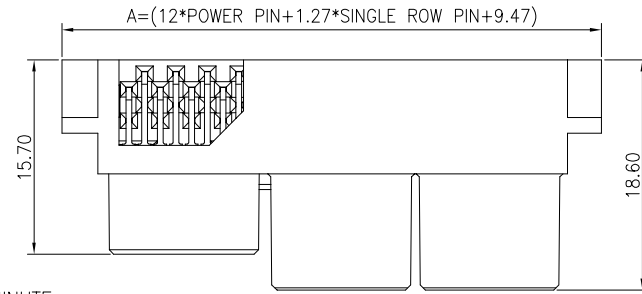
4.MAX PROCESSING TEMP:265°C SECONDS 10S

5.OPERATION TEMPERATURE:-40°C TO +105°C.

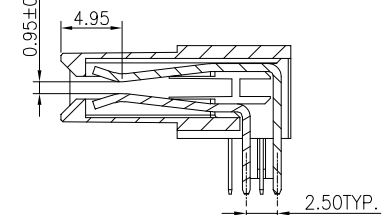
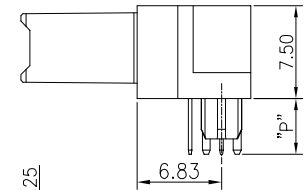
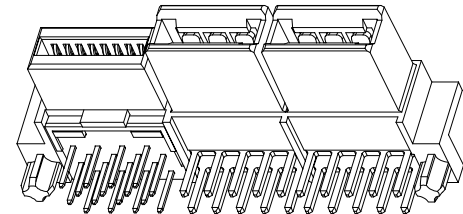
6.ORDER INFORMATION:

62F5-F XXX XXX S4 075 C 0X

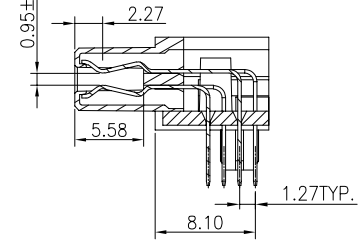
				流水码:
电源Pin数	信号Pin数	端子电镀:	塑胶高度:	01=2.90("P")
002=2*01PIN	012=2*06PIN	S0=Gold Flash/Tin	075=7.50mm	02=3.60("P")
~	~	(半金锡)		03=4.50("P")
012=2*06PIN	040=2*20PIN	S1=1u" Gold/Tin		
		S2=3u" Gold/Tin		
		S3=5u" Gold/Tin		
		S4=10u" Gold/Tin		
		S5=15u" Gold/Tin		
		S6=30u" Gold/Tin		



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE ± 0.05



SECTION A-A



SECTION B-B

流水码	"P" 焊脚长度	PCB 厚度
01	2.90	1.57
02	3.60	2.36
03	4.50	3.18

					OPERATION		DRAW	Mr.Zeng	2025.03.17	SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.					
					X.X	±0.40	DESIGN	Jensen	2025.03.17						
					X.XX	±0.25	CHECK	Jack	2025.03.17						
					X.XXX	±0.15	APPROVE	Andy	2025.03.17						
A0		NEW		——	——	Angle	±3°			SHEET	1/1	TITLE:	母座 电源+信号连接器 卧式90° DIP 无导柱 带定位柱		
REV	DATE	MODIFICATION DESCRIPTION		CHANGE	APPROVE	DIM.	TOL	UNIT	mm	SCALE	1:1	PROJ.		DRAW NO.	SP-1472

客户图

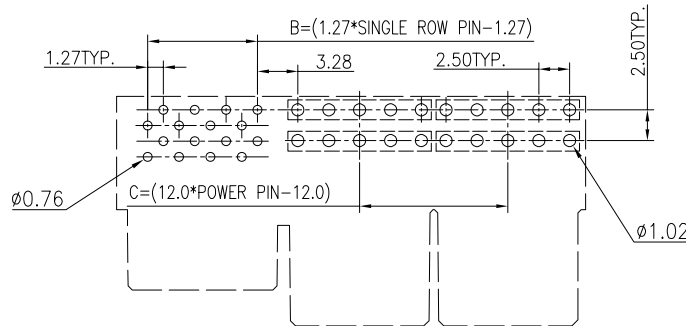
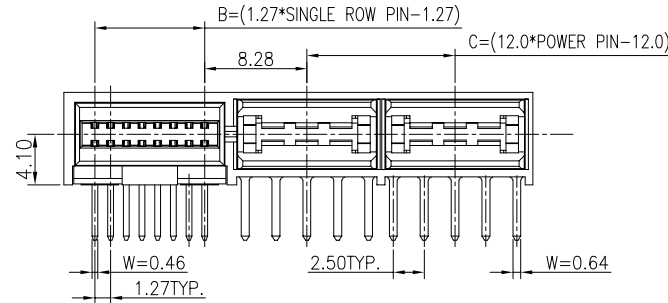
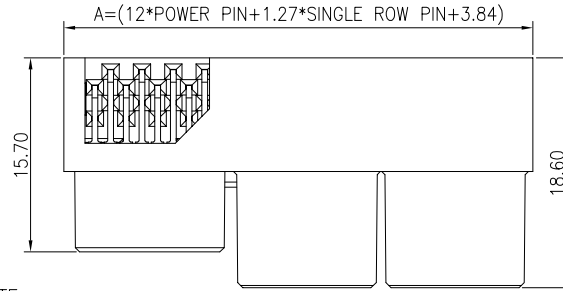
NOTES:

- 1.FINISH:
 - 1.1 HOUSING: LCP,UL94V-0,BLACK
 - 1.2 COVER: LCP,UL94V-0,BLACK
 - 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA
2. ELECTRICAL:
 - 2.1 CURRENT RATING: SIGNAL PIN 1.0A.
POWER PIN 30A.
 - 2.2 DIELECTRIC WITHSTANDING VOLTAGE: SIGNAL PIN 500V DC/MINUTE.
POWER PIN 1000V DC/MINUTE.
 - 2.3 CONTACT RESISTANCE: SIGNAL PIN 45mΩ MAX.AT DC 20mA.
POWER PIN 2mΩ MAX.AT DC 20mA.
 - 2.4 INSULATION RESISTANCE: SIGNAL PIN 500V DC/1000MΩ MIN
POWER PIN 500V DC/5000MΩ MIN
- 3.SALT SPRAY TEST:
 - 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.MAX PROCESSING TEMP:265°C SECONDS 10S
- 5.OPERATION TEMPERATURE:-40°C TO +105°C.
- 6.ORDER INFORMATION:

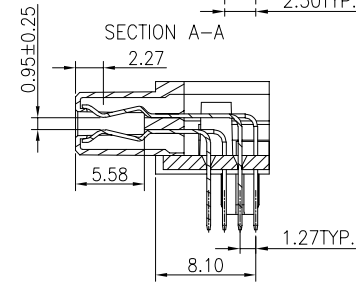
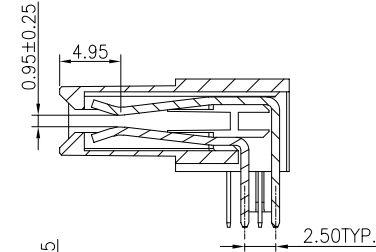
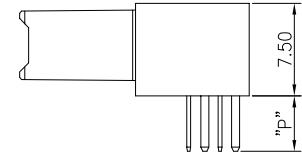
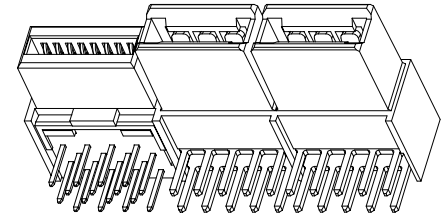
W62F5-F XXX XXX S4 075 C 0X

电源Pin数	信号Pin数	端子电镀:	塑胶高度:	流水码:
002=2*01PIN	012=2*06PIN	S0=Gold Flash/Tin	075=7.50mm	01=2.90("P")
~	~	(半金锡)		02=3.60("P")
012=2*06PIN	040=2*20PIN	S1=1u" Gold/Tin		03=4.50("P")
		S2=3u" Gold/Tin		
		S3=5u" Gold/Tin		
		S4=10u" Gold/Tin		
		S5=15u" Gold/Tin		
		S6=30u" Gold/Tin		

流水码	"P" 焊脚长度	PCB 厚度
01	2.90	1.57
02	3.60	2.36
03	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05



SECTION B-B

					OPERATION	DRAW	Mr.Zeng	2025.03.17	SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					X.X ±0.40	DESIGN	Jensen	2025.03.17				
					X.XX ±0.25	CHECK	Jack	2025.03.17				
					X.XXX ±0.15	APPROVE	Andy	2025.03.17				
A0		NEW			Angle ±3°				SHEET	1/1	TITLE:	母座 电源+信号连接器 卧式30° DIP 无导柱 无定位柱
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM. TOL	UNIT	mm	SCALE	1:1	PROJ.	DRAW NO.	SP-1473

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: 1.0A./PIN
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: 45mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: 500V DC/1000MΩ MIN

3.SALT SPRAY TEST:

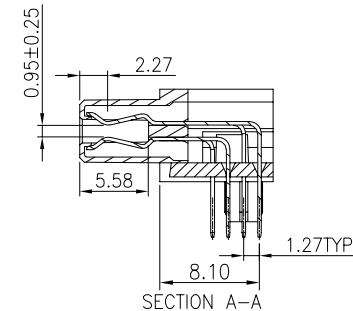
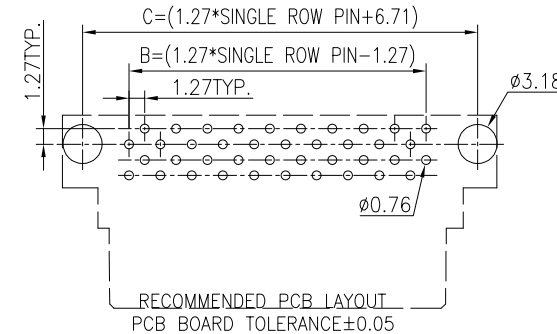
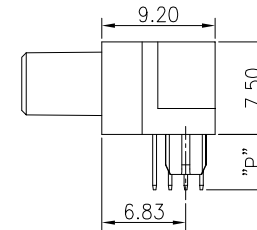
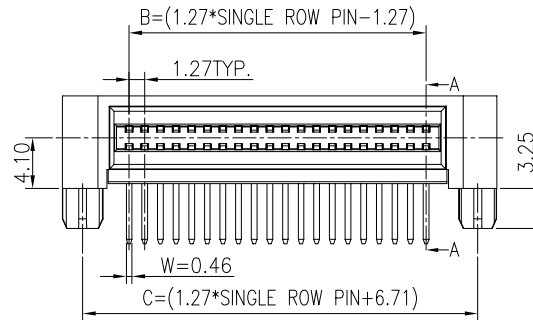
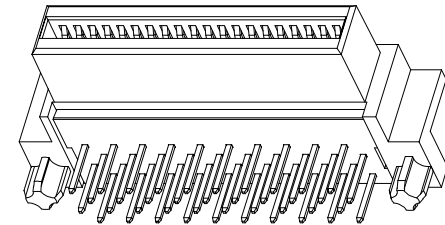
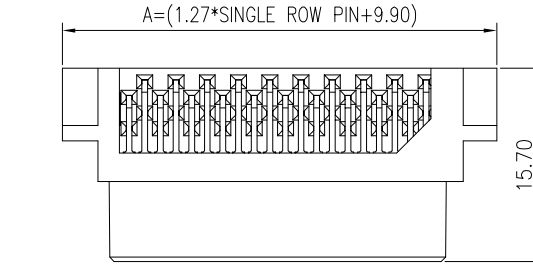
- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.MAX PROCESSING TEMP:265°C SECONDS 10S
- 5.OPERATION TEMPERATURE:-40°C TO +105°C.

6.ORDER INFORMATION:

62F5-F XXX S4 075 C 1X

信号Pin数	端子电镀:	塑胶高度:	流水码:
012=2*06PIN	S0=Gold Flash/Tin (半金锡)	075=7.50mm	11=2.90 ("P")
040=2*20PIN	S1=1u" Gold/Tin		12=3.60 ("P")
	S2=3u" Gold/Tin		13=4.50 ("P")
	S3=5u" Gold/Tin		
	S4=10u" Gold/Tin		
	S5=15u" Gold/Tin		
	S6=30u" Gold/Tin		

流水码	"P" 焊脚长度	PCB 厚度
11	2.90	1.57
12	3.60	2.36
13	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05

					OPERATION		DRAW		Mr.Zeng	2025.03.17		SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.				
					X.X	±0.40	DESIGN		Jensen	2025.03.17						
					X.XX	±0.25	CHECK		Jack	2025.03.17		SIZE	A4	PART NO.	62F5—F XXX S4 075 C 1X	
AO		NEW		——	X.XXX	±0.15	APPROVE		Andy	2025.03.17		SHEET	1/1	TITLE:	母座 信号连接器 卧式90° DIP 无导柱 带定位柱	
REV	DATE	MODIFICATION DESCRIPTION		CHANGE	APPROVE	Angle	±3°									
						DIM.	TOL	UNIT		mm	SCALE	1:1	PROJ.		DRAW NO.	SP—1480

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: 1.0A./PIN
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: 45mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: 500V DC/1000MΩ MIN

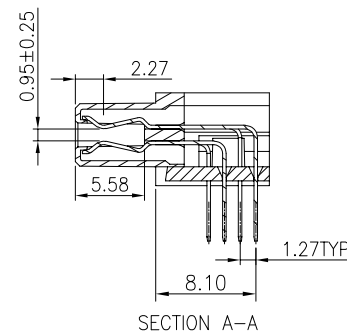
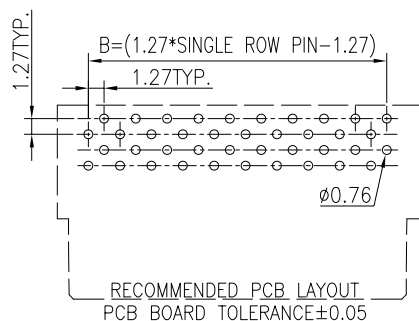
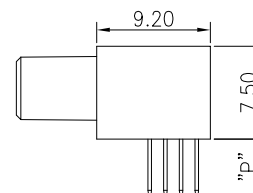
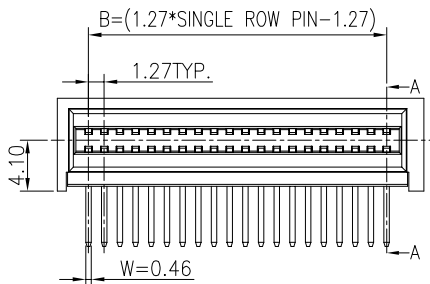
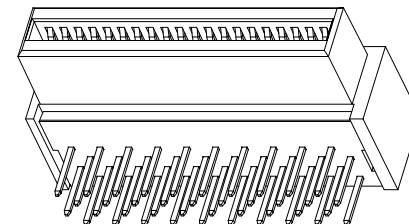
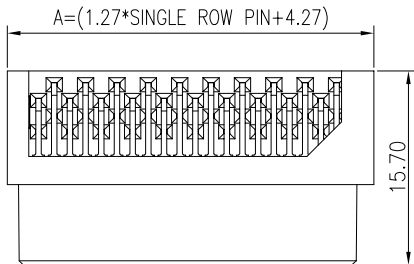
3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.MAX PROCESSING TEMP:265°C SECONDS 10S
- 5.OPERATION TEMPERATURE:-40°C TO +105°C.
- 6.ORDER INFORMATION:

W62F5-F XXX S4 075 C 1X

信号Pin数	端子电镀:	塑胶高度:	流水码:
012=2*06PIN	S0=Gold Flash/Tin	075=7.50mm	11=2.90 ("P")
~	(半金锡)		12=3.60 ("P")
040=2*20PIN	S1=1u" Gold/Tin		13=4.50 ("P")
	S2=3u" Gold/Tin		
	S3=5u" Gold/Tin		
	S4=10u" Gold/Tin		
	S5=15u" Gold/Tin		
	S6=30u" Gold/Tin		

流水码	"P" 焊脚长度	PCB 厚度
11	2.90	1.57
12	3.60	2.36
13	4.50	3.18



					OPERATION	DRAW	Mr.Zeng	2025.03.17	SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					X.X ±0.40	DESIGN	Jensen	2025.03.17				
					X.XX ±0.25	CHECK	Jack	2025.03.17				
					X.XXX ±0.15	APPROVE	Andy	2025.03.17				
A0			NEW		Angle ±3°				SIZE	A4	PART NO.	W62F5-F XXX S4 075 C 1X
REV	DATE		MODIFICATION DESCRIPTION	CHANGE	DIM.	TOL	UNIT	mm	SCALE	1:1	TITLE:	母座 信号连接器 卧式90° DIP无导柱 无定位柱
									PROJ.	Φ	DRAW NO.	SP-1480

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: 30A.
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 1000V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: 2mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: 500V DC/5000MΩ MIN

3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST

- 4.MAX PROCESSING TEMP:265°C SECONDS 10S

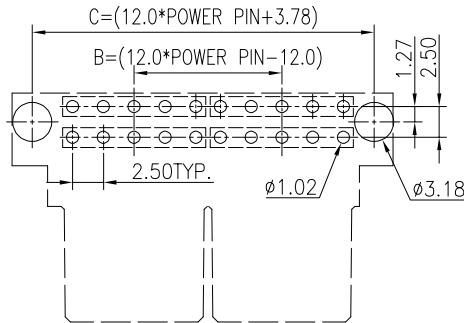
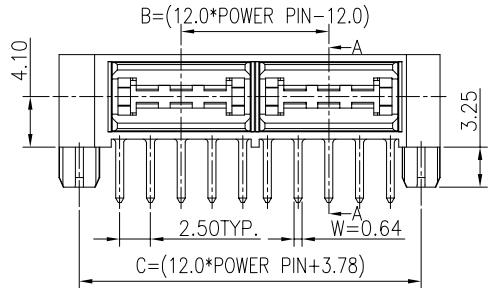
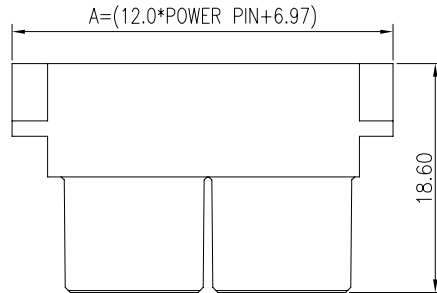
- 5.OPERATION TEMPERATURE:-40°C TO +105°C.

6.ORDER INFORMATION:

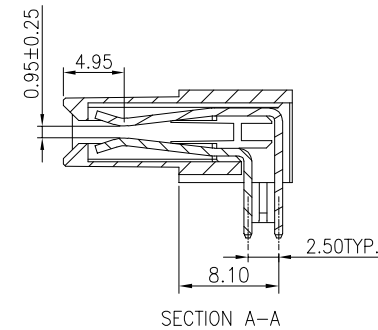
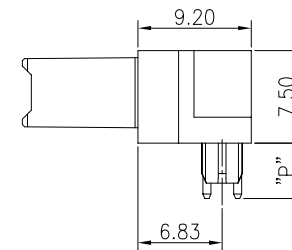
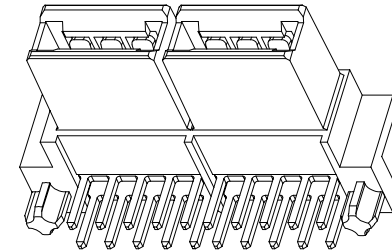
62F5-F XXX S4 075 C 2X

电源Pin数	端子电镀:	塑胶高度:	流水码:
002=2*01PIN	S0=Gold Flash/Tin	075=7.50mm	21=2.90("P")
~	(半金锡)		22=3.60("P")
012=2*06PIN	S1=1u" Gold/Tin		23=4.50("P")
	S2=3u" Gold/Tin		
	S3=5u" Gold/Tin		
	S4=10u" Gold/Tin		
	S5=15u" Gold/Tin		
	S6=30u" Gold/Tin		

流水码	"P" 焊脚长度	PCB 厚度
21	2.90	1.57
22	3.60	2.36
23	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05



OPERATION

Mr.Zeng

2025.03.17

Jensen

2025.03.17

Jack

2025.03.17

Andy

2025.03.17

UNIT

mm

SCALE

1:1

DRAW

DESIGN

CHECK

APPROVE

Angle

±3°

DIM.

TOL

Mr.Zeng

Jensen

Jack

Andy

UNIT

mm

SCALE

1:1

SOLEPIN 东莞市硕品电子有限公司
PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE A4 PART NO. 62F5-F XXX S4 075 C 2X

SHEET 1/1 TITLE: 电源连接器 母座 卧式90° 无导柱 带定位柱

PROJ. DRAW NO. SP-1487

REV

DATE

MODIFICATION

DESCRIPTION

CHANGE

APPROVE

NEW

DATE

MODIFICATION

DESCRIPTION

CHANGE

APPROVE

NEW

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: 30A.
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 1000V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: 2mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: 500V DC/5000MΩ MIN

3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST

4.MAX PROCESSING TEMP:265°C SECONDS 10S

5.OPERATION TEMPERATURE:-40°C TO +105°C.

6.ORDER INFORMATION:

W62F5-F XXX S4 075 C 2X

流水码:

21=2.90("P")

22=3.60("P")

23=4.50("P")

电源Pin数

端子电镀:

塑胶高度:

002=2*01PIN

S0=Gold Flash/Tin 075=7.50mm

(半金锡)

012=2*06PIN

S1=1u" Gold/Tin

S2=3u" Gold/Tin

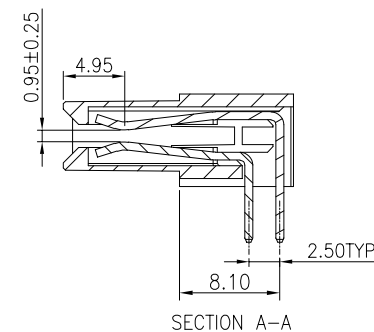
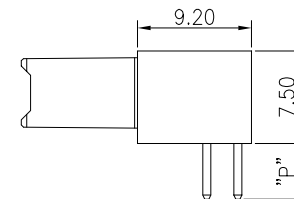
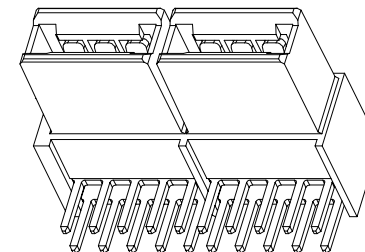
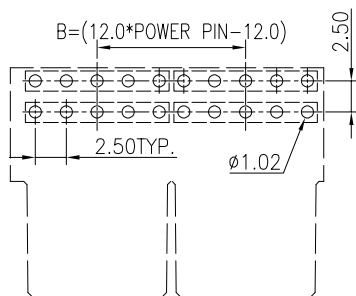
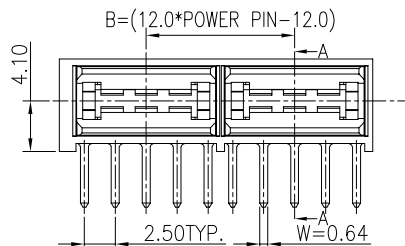
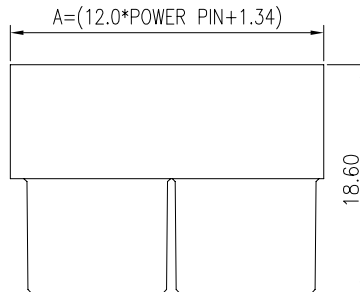
S3=5u" Gold/Tin

S4=10u" Gold/Tin

S5=15u" Gold/Tin

S6=30u" Gold/Tin

流水码	"P" 焊脚长度	PCB 厚度
21	2.90	1.57
22	3.60	2.36
23	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05

					OPERATION		DRAW		Mr.Zeng		2025.03.17		SOLEPiN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.							
					X.X	±0.40	DESIGN		Jensen		2025.03.17									
					X.XX	±0.25	CHECK		Jack		2025.03.17						SIZE	A4	PART NO.	W62F5-F XXX S4 075 C 2X
					X.XXX	±0.15	APPROVE				2025.03.17						SHEET	1/1	TITLE:	电源连接器 母座 卧式90° 无导柱 无定位柱
A0		NEW		——	——	Angle	±3°			Andy		2025.03.17								
REV	DATE	MODIFICATION DESCRIPTION		CHANGE	APPROVE	DIM.	TOL	UNIT		mm	SCALE	1:1	PROJ.		DRAW NO.	SP-1488				

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: SIGNAL PIN 1.0A.
POWER PIN 30A.
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: SIGNAL PIN 500V DC/MINUTE.
POWER PIN 1000V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: SIGNAL PIN 45mΩ MAX.AT DC 20mA.
POWER PIN 2mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: SIGNAL PIN 500V DC/1000MΩ MIN
POWER PIN 500V DC/5000MΩ MIN

3.SALT SPRAY TEST:

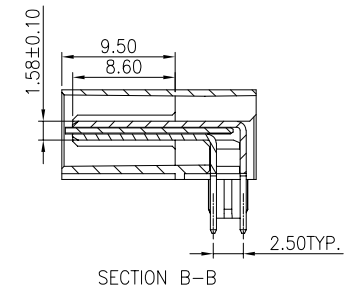
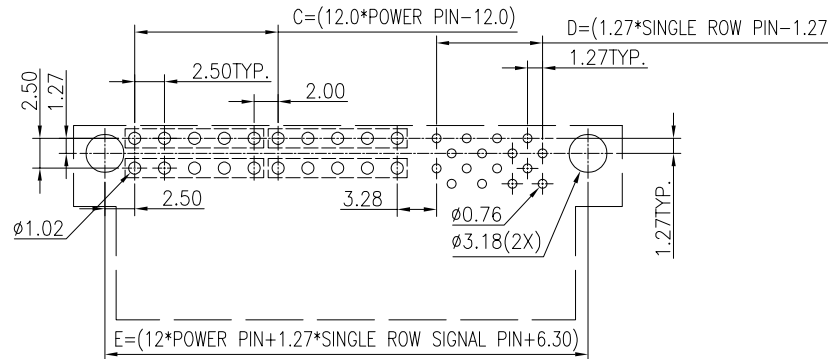
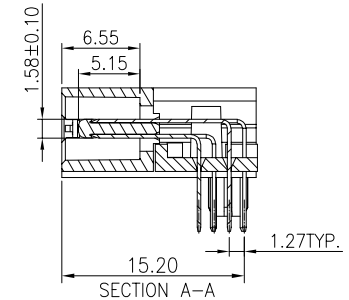
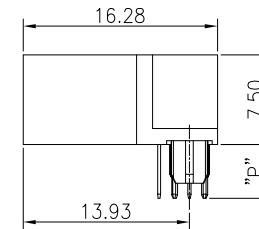
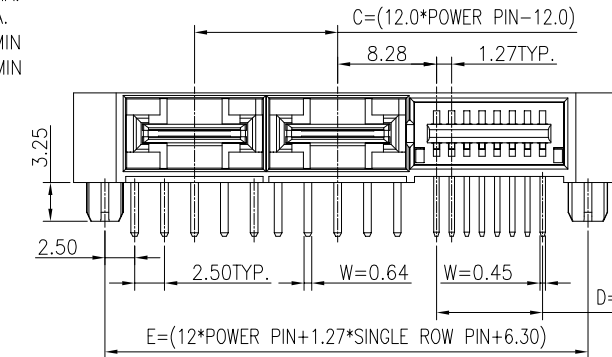
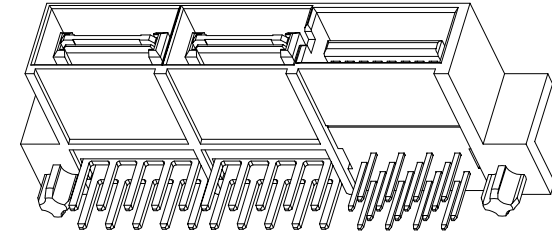
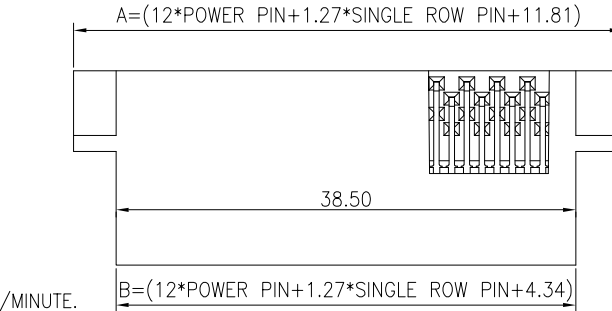
- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.MAX PROCESSING TEMP:265°C SECONDS 10S
- 5.OPERATION TEMPERATURE:-40°C TO +105°C.

6.ORDER INFORMATION:

62F5-M XXX XXX S4 075 C 0X

流水码: 01=2.90("P")
02=3.60("P")
03=4.50("P")
电源Pin数 信号Pin数 端子电镀: 塑胶高度: 02=3.60("P")
002=2*01PIN 012=2*06PIN S0=Gold Flash/Tin 075=7.50mm (半金锡)
~ 012=2*06PIN 040=2*20PIN S1=1u" Gold/Tin
S2=3u" Gold/Tin
S3=5u" Gold/Tin
S4=10u" Gold/Tin
S5=15u" Gold/Tin
S6=30u" Gold/Tin

流水码	"P" 焊脚长度	PCB 厚度
01	2.90	1.57
02	3.60	2.36
03	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05

				OPERATION		DRAW		Mr.Zeng		2025.03.17		SOLEPIN 东莞市硕品电子有限公司			
				X.X		±0.40		DESIGN		Jensen		2025.03.17		PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.	
				X.XX		±0.25		CHECK		Jack		2025.03.17		SIZE A4	
				X.XXX		±0.15		APPROVE		Andy		2025.03.17		PART NO.	
A0				Angle		±3°		SHEET		1/2		TITLE:		62F5-M XXX XXX S4 075 C 0X	
REV				DIM.		TOL		UNIT		mm		SCALE		DRAW NO.	
														SP-1468	

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: SIGNAL PIN 1.0A.
POWER PIN 30A.
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: SIGNAL PIN 500V DC/MINUTE.
POWER PIN 1000V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: SIGNAL PIN 45mΩ MAX.AT DC 20mA.
POWER PIN 2mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: SIGNAL PIN 500V DC/1000MΩ MIN
POWER PIN 500V DC/5000MΩ MIN

3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST

4.MAX PROCESSING TEMP:265°C SECONDS 10S

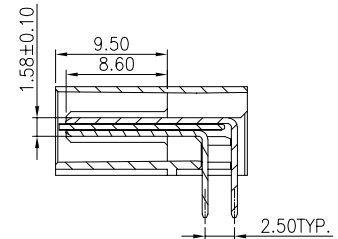
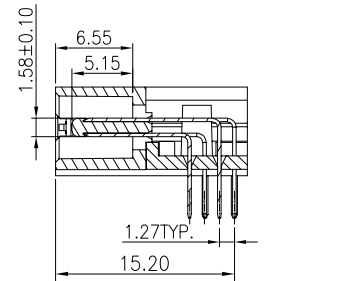
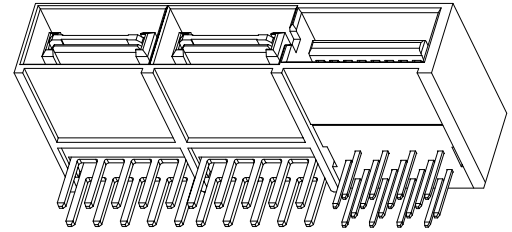
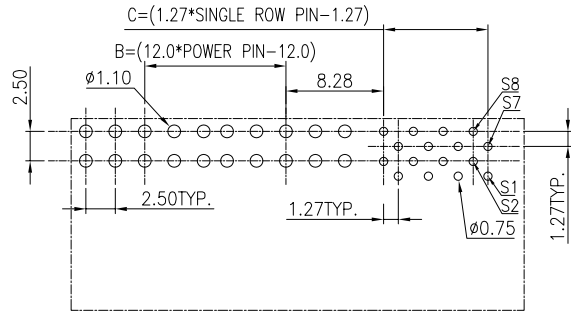
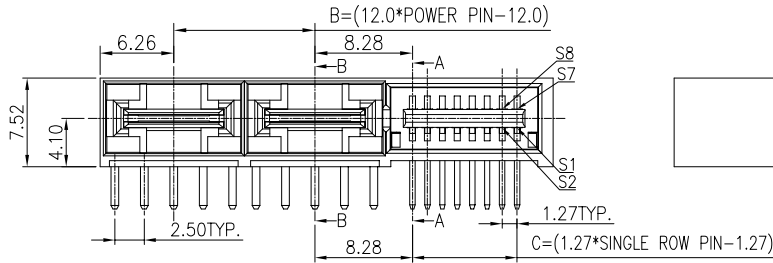
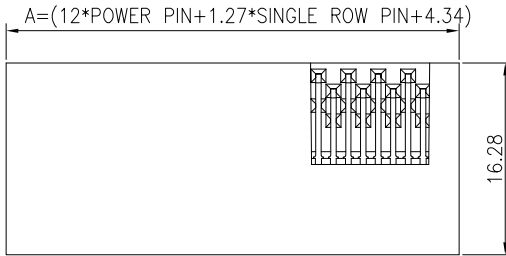
5.OPERATION TEMPERATURE:-40°C TO +105°C.

6.ORDER INFORMATION:

W62F5-M XXX XXX S4 075 C 0X

电源Pin数	信号Pin数	端子电镀:	塑胶高度:	流水码:
002=2*01PIN	012=2*06PIN	S0=Gold Flash/Tin	075=7.50mm	01=2.90("P")
~	~	(半金锡)		02=3.60("P")
012=2*06PIN	040=2*20PIN	S1=1u" Gold/Tin		03=4.50("P")
		S2=3u" Gold/Tin		
		S3=5u" Gold/Tin		
		S4=10u" Gold/Tin		
		S5=15u" Gold/Tin		
		S6=30u" Gold/Tin		

流水码	"P" 焊脚长度	PCB 厚度
01	2.90	1.57
02	3.60	2.36
03	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05

OPERATION		DRAW		Mr.Zeng		2025.03.17	
X.X	±0.40	DESIGN	Jensen	2025.03.17			
X.XX	±0.25	CHECK	Jack	2025.03.17			
X.XXX	±0.15	APPROVE	Andy	2025.03.17			
Angle	±3°						
DIM.	TOL	UNIT	mm	SCALE	1:1		

SOLEPIN 东莞市硕品电子有限公司
PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE	A4	PART NO.	W62F5-M XXX XXX S4 075 C 0X				
SHEET	1/1	TITLE:	62F5 公头电源+信号连接器 90° 无导柱 无定位柱				
PROJ.	☞	DRAW NO.	SP-1469				

客户图

NOTES:

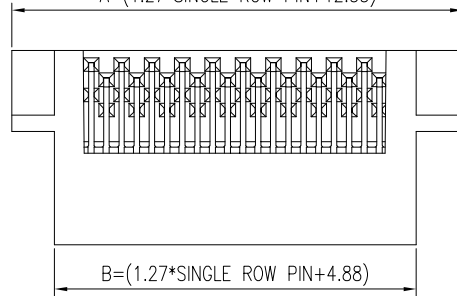
- 1.FINISH:
 - 1.1 HOUSING: LCP,UL94V-0,BLACK
 - 1.2 COVER: LCP,UL94V-0,BLACK
 - 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA
2. ELECTRICAL:
 - 2.1 CURRENT RATING: 1.0A./PIN
 - 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V DC/MINUTE.
 - 2.3 CONTACT RESISTANCE: 45mΩ MAX.AT DC 20mA.
 - 2.4 INSULATION RESISTANCE: 500V DC/1000MΩ MIN
- 3.SALT SPRAY TEST:
 - 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST
 - 4.MAX PROCESSING TEMP:265°C SECONDS 10S
 - 5.OPERATION TEMPERATURE:-40°C TO +105°C.
 - 6.ORDER INFORMATION:

62F5-M XXX S4 075 C 1X

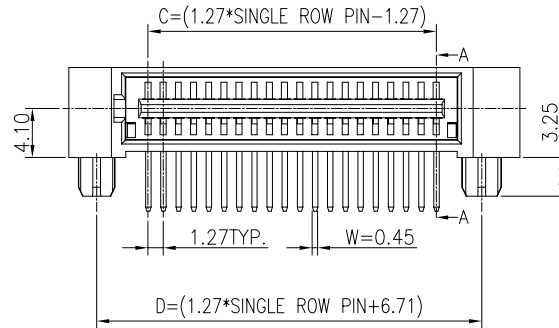
信号Pin数	端子电镀:	塑胶高度:	流水码:
012=2*06PIN	S0=Gold Flash/Tin	075=7.52mm	11=2.90("P")
~	(半金锡)		12=3.60("P")
040=2*20PIN	S1=1u" Gold/Tin		13=4.50("P")
	S2=3u" Gold/Tin		
	S3=5u" Gold/Tin		
	S4=10u" Gold/Tin		
	S5=15u" Gold/Tin		
	S6=30u" Gold/Tin		

流水码	"P" 焊脚长度	PCB 厚度
11	2.90	1.57
12	3.60	2.36
13	4.50	3.18

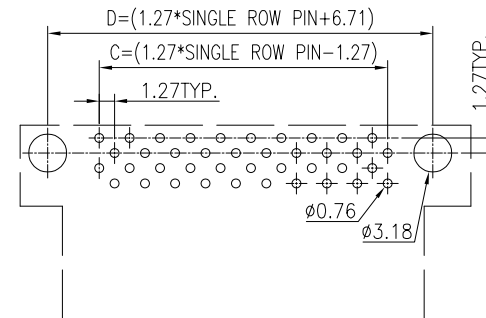
$$A=(1.27*\text{SINGLE ROW PIN}+12.35)$$



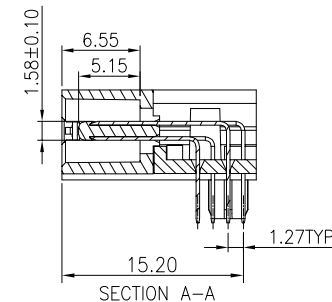
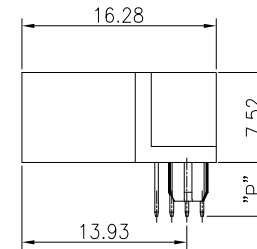
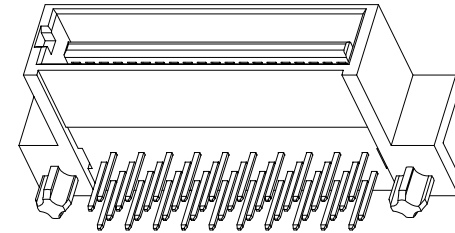
$$B=(1.27*\text{SINGLE ROW PIN}+4.88)$$



$$D=(1.27*\text{SINGLE ROW PIN}+6.71)$$



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05



OPERATION

DRAW

Mr.Zeng

2025.03.17

X.X ±0.40

X.XX ±0.25

X.XXX ±0.15

Angle ±3°

DIM. TOL

UNIT

Jensen

2025.03.17

Jack

2025.03.17

Andy

2025.03.17

mm

SCALE

1:1

SOLEPIN 东莞市硕品电子有限公司
PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE A4 PART NO. 62F5-M XXX S4 075 C 1X

SHEET 1/1 TITLE: 公头 信号连接器 90° DIP 无导柱 带定位柱

PROJ. DRAW NO. SP-1476

REV

DATE

MODIFICATION DESCRIPTION

CHANGE

APPROVE

NEW

1

2

3

4

5

6

7

8

9

10

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: 1.0A./PIN
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: 45mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: 500V DC/1000MΩ MIN

3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.MAX PROCESSING TEMP:265°C SECONDS 10S
- 5.OPERATION TEMPERATURE:-40°C TO +105°C.
- 6.ORDER INFORMATION:

W62F5-M XXX S4 075 C 1X

信号Pin数

012=2*06PIN

~

040=2*20PIN

端子电镀:

S0=Gold Flash/Tin

(半金锡)

S1=1u" Gold/Tin

S2=3u" Gold/Tin

S3=5u" Gold/Tin

S4=10u" Gold/Tin

S5=15u" Gold/Tin

S6=30u" Gold/Tin

塑胶高度:

075=7.52mm

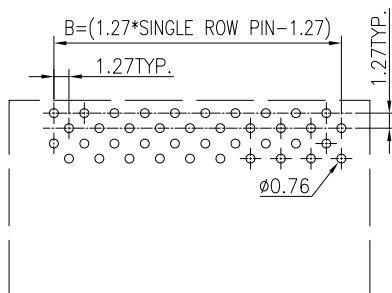
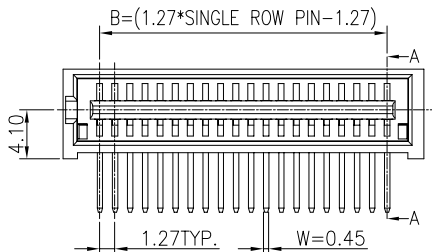
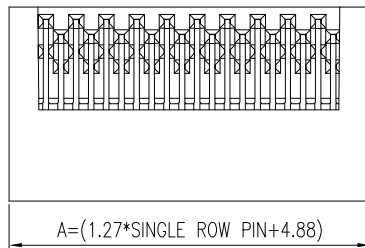
流水码:

11=2.90("P")

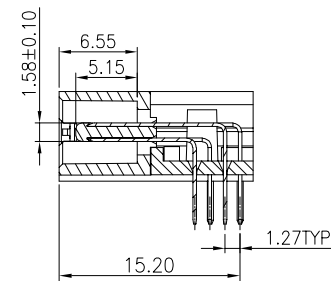
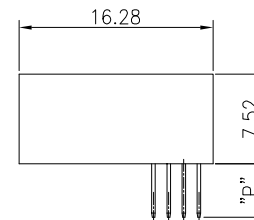
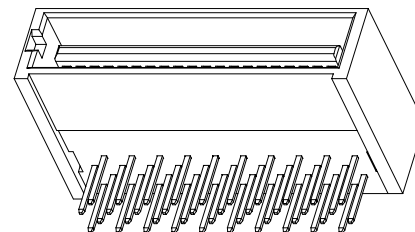
12=3.60("P")

13=4.50("P")

流水码	"P" 焊脚长度	PCB 厚度
11	2.90	1.57
12	3.60	2.36
13	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05



SECTION A-A

					OPERATION	DRAW	Mr.Zeng	2025.03.17	SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					X.X ±0.40	DESIGN	Jensen	2025.03.17				
					X.XX ±0.25	CHECK	Jack	2025.03.17	SIZE	A4	PART NO.	W62F5-M XXX S4 075 C 1X
					X.XXX ±0.15	APPROVE	Andy	2025.03.17	SHEET	1/1	TITLE:	公头 信号连接器 90° DIP 无导柱 无定位柱
A0			NEW		Angle ±3°				PROJ.	☯	DRAW NO.	SP-1477
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM. TOL	UNIT	mm	SCALE	1:1			

客户图

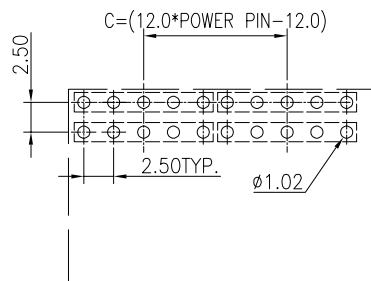
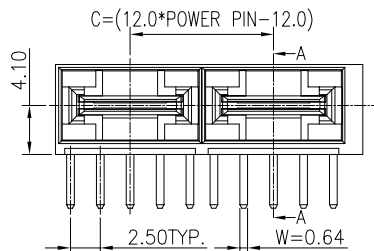
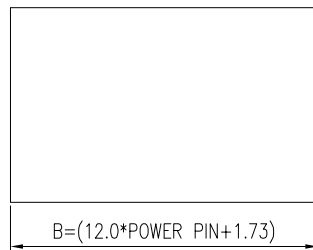
NOTES:

- 1.FINISH:
 - 1.1 HOUSING: LCP,UL94V-0,BLACK
 - 1.2 COVER: LCP,UL94V-0,BLACK
 - 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA
2. ELECTRICAL:
 - 2.1 CURRENT RATING: 30A.
 - 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 1000V DC/MINUTE.
 - 2.3 CONTACT RESISTANCE: 2mΩ MAX.AT DC 20mA.
 - 2.4 INSULATION RESISTANCE: 500V DC/5000MΩ MIN
- 3.SALT SPRAY TEST:
 - 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.MAX PROCESSING TEMP:265°C SECONDS 10S
- 5.OPERATION TEMPERATURE:-40°C TO +105°C.
- 6.ORDER INFORMATION:

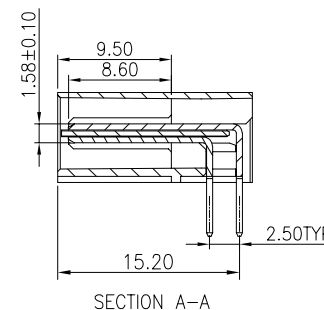
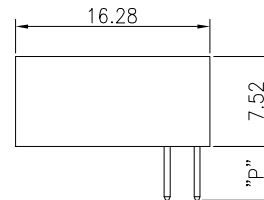
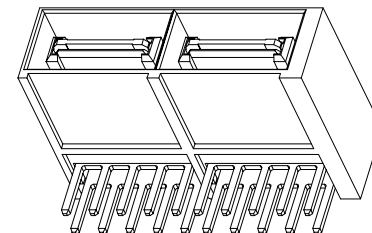
W62F5-M XXX S4 075 C 2X

			流水码:
电源Pin数	端子电镀:	塑胶高度:	21=2.90("P")
002=2*01PIN	S0=Gold Flash/Tin	075=7.52mm	22=3.60("P")
~	(半金锡)		23=4.50("P")
012=2*06PIN	S1=1u" Gold/Tin		
	S2=3u" Gold/Tin		
	S3=5u" Gold/Tin		
	S4=10u" Gold/Tin		
	S5=15u" Gold/Tin		
	S6=30u" Gold/Tin		

流水码	"P" 焊脚长度	PCB 厚度
21	2.90	1.57
22	3.60	2.36
23	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05



					OPERATION		DRAW		Mr.Zeng		2025.03.17		SOLEPIN 东莞市硕品电子有限公司 PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					X.X	±0.40	DESIGN		Jensen		2025.03.17					
					X.XX	±0.25	CHECK		Jack		2025.03.17		SIZE	A4	PART NO.	W62F5—M XXX S4 075 C 2X
A0		NEW			X.XXX	±0.15	APPROVE		Andy		2025.03.17		SHEET	1/1	TITLE:	公头 电源连接器 90° 无导柱 无定位柱
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	Angle	±3°	DIM.	TOL	UNIT	mm	SCALE	1:1	PROJ.		DRAW NO.	SP—1484

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: 30A.
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 1000V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: 2mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: 500V DC/5000MΩ MIN

3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST

4.MAX PROCESSING TEMP:265°C SECONDS 10S

5.OPERATION TEMPERATURE:-40°C TO +105°C.

6.ORDER INFORMATION:

62F5-M XXX S4 075 C 2X

电源Pin数

002=2*01PIN

~

012=2*06PIN

端子电镀:

S0=Gold Flash/Tin

(半金锡)

S1=1u" Gold/Tin

S2=3u" Gold/Tin

S3=5u" Gold/Tin

S4=10u" Gold/Tin

S5=15u" Gold/Tin

S6=30u" Gold/Tin

塑胶高度:

075=7.52mm

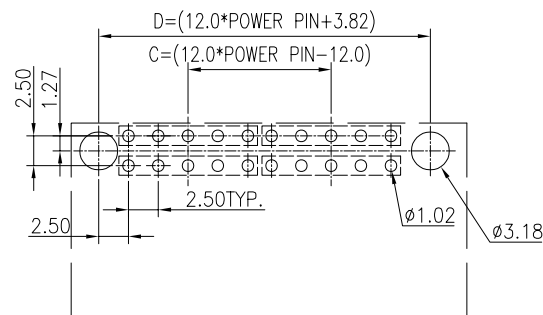
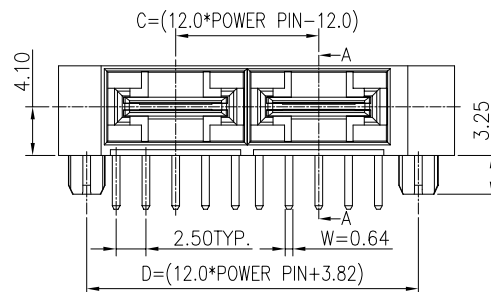
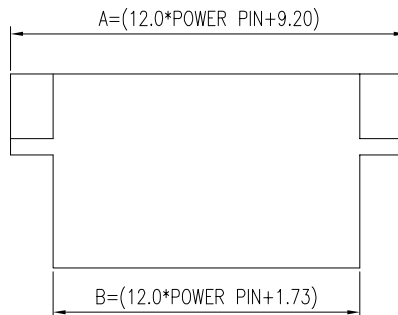
流水码:

21=2.90 ("P")

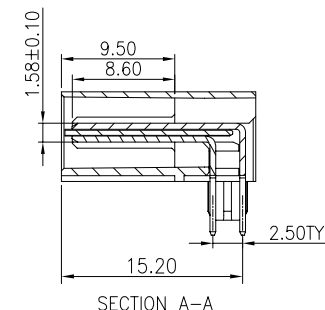
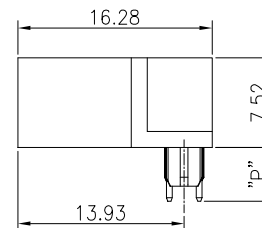
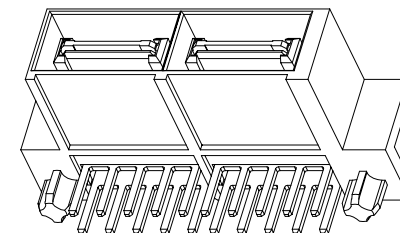
22=3.60 ("P")

23=4.50 ("P")

流水码	"P" 焊脚长度	PCB 厚度
21	2.90	1.57
22	3.60	2.36
23	4.50	3.18



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05



OPERATION

X.X ±0.40

X.XX ±0.25

X.XXX ±0.15

Angle ±3°

DIM. TOL

DRAW

DESIGN

CHECK

APPROVE

UNIT

Mr.Zeng

Jensen

Jack

Andy

mm

2025.03.17

2025.03.17

2025.03.17

2025.03.17

SCALE

1:1

SOLEPIN 东莞市硕品电子有限公司
PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE A4 PART NO. 62F5-M XXX S4 075 C 2X

SHEET 1/1 TITLE: 公头 电源连接器 90° 无导柱 带定位柱

PROJ. DRAW NO. SP-1483

A0 NEW

REV DATE MODIFICATION DESCRIPTION

CHANGE APPROVE

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: SIGNAL PIN 1.0A.
POWER PIN 30A.
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: SIGNAL PIN 500V DC/MINUTE.
POWER PIN 1000V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: SIGNAL PIN 45mΩ MAX.AT DC 20mA.
POWER PIN 2mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: SIGNAL PIN 500V DC/1000MΩ MIN
POWER PIN 500V DC/5000MΩ MIN

3.SALT SPRAY TEST:

3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST

4.MAX PROCESSING TEMP:265°C SECONDS 10S

5.OPERATION TEMPERATURE:-40°C TO +105°C.

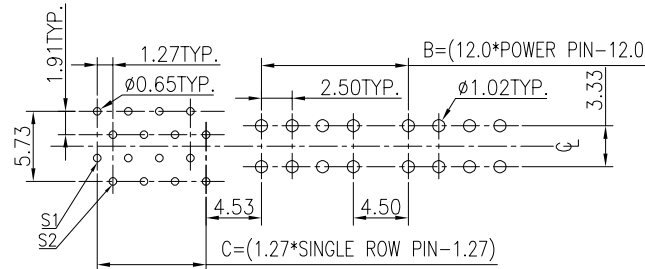
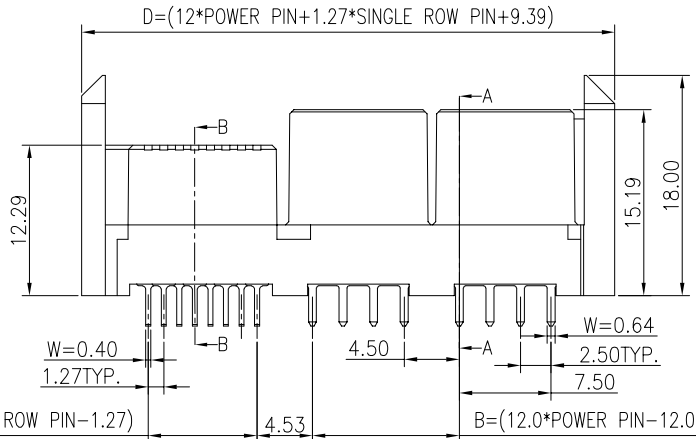
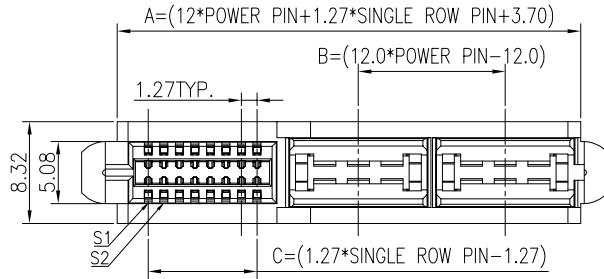
6.ORDER INFORMATION:

62F4V-F XXX XXX S4 180 C 0X

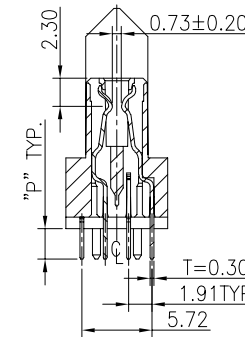
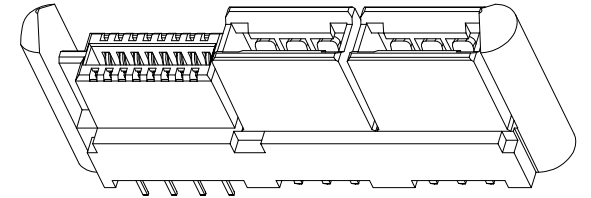
流水码:
01="P"/"Q"
02="P"/"Q"
03="P"/"Q"

电源Pin数 信号Pin数 端子电镀: 塑胶高度: 02="P"/"Q"
002=2*01PIN 012=2*06PIN S0=Gold Flash/Tin 180=18.00mm 03="P"/"Q"
(半金锡)
~ 012=2*06PIN 040=2*20PIN S1=1u" Gold/Tin
S2=3u" Gold/Tin
S3=5u" Gold/Tin
S4=10u" Gold/Tin
S5=15u" Gold/Tin
S6=30u" Gold/Tin

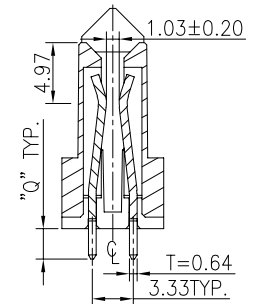
流水码	"P" 信号焊脚长度	"Q" 电源焊脚长度
01	2.35	2.31
02	2.58	2.51
03	3.13	3.06



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE ±0.05



SECTION B-B



SECTION A-A

OPERATION

DRAW

Mr.Zeng

2025.03.17

DESIGN

Jensen

2025.03.17

CHECK

Jack

2025.03.17

APPROVE

Andy

2025.03.17

SOLEPiN 东莞市硕品电子有限公司
PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

SIZE A4 PART NO. 62F4V-F XXX XXX S4 180 C 0X

SHEET 1/1 TITLE: 母座 电源+信号连接器 立式180° DIP 带导柱

PROJ. DRAW NO. SP-1490

UNIT mm SCALE 1:1

DIM. TOL

CHANGE APPROVE

MODIFICATION DESCRIPTION

DATE

REV

NEW

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

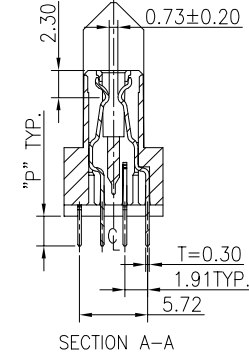
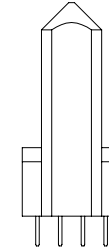
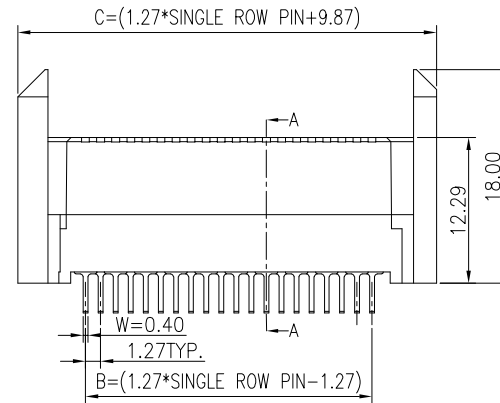
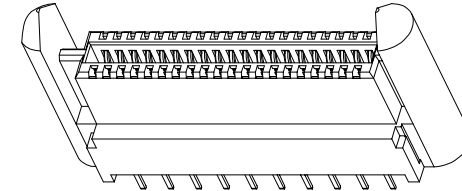
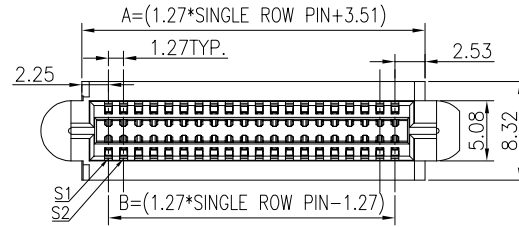
- 2.1 CURRENT RATING: 1.0A./PIN
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 500V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: 45mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: 500V DC/1000MΩ MIN

3.SALT SPRAY TEST:

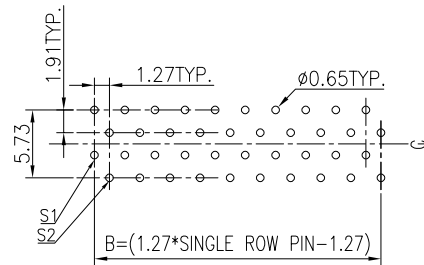
- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST
- 4.MAX PROCESSING TEMP:265°C SECONDS 10S
- 5.OPERATION TEMPERATURE:-40°C TO +105°C.
- 6.ORDER INFORMATION:

62F4V-F XXX S4 180 C 1X

信号Pin数	端子电镀:	塑胶高度:	流水码:
012=2*06PIN	S0=Gold Flash/Tin (半金锡)	12=2.58("P")	11=2.35("P")
040=2*20PIN	S1=1u" Gold/Tin	13=3.13("P")	
	S2=3u" Gold/Tin		
	S3=5u" Gold/Tin		
	S4=10u" Gold/Tin		
	S5=15u" Gold/Tin		
	S6=30u" Gold/Tin		



流水码	"P" 信号焊脚长度
11	2.35
12	2.58
13	3.13



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE ±0.05

OPERATION

DRAW

Mr.Zeng

2025.03.17

SOLEPIN 东莞市硕品电子有限公司
PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

X.X ±0.40

DESIGN

Jensen

2025.03.17

X.XX ±0.25

CHECK

Jack

2025.03.17

X.XXX ±0.15

APPROVE

Andy

2025.03.17

Angle ±3°

PROJ.

1/1

TITLE:

母座 信号连接器 立式180° DIP 带导柱

DIM. TOL

UNIT

mm

SCALE

DRAW NO. SP-1491

REV

DATE

MODIFICATION DESCRIPTION

CHANGE

APPROVE

客户图

NOTES:

1.FINISH:

- 1.1 HOUSING: LCP,UL94V-0,BLACK
- 1.2 COVER: LCP,UL94V-0,BLACK
- 1.3 CONTACT: COPPER ALLOY,
PLATED IN CONTACT AREA,GOLD
NICKEL-PLATED BASE THROUGHOUT THE TERMINAL.
MIST TIN IN THE SOLDER AREA

2. ELECTRICAL:

- 2.1 CURRENT RATING: 30A.
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 1000V DC/MINUTE.
- 2.3 CONTACT RESISTANCE: 2mΩ MAX.AT DC 20mA.
- 2.4 INSULATION RESISTANCE: 500V DC/5000MΩ MIN

3.SALT SPRAY TEST:

- 3.1 CONCENTRATION IS 5%, THE TEMPERATURE IS 35±2°C,
TEST TIME 8H MIN,NO OXIDATION OR RUST

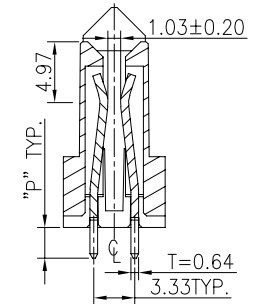
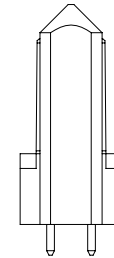
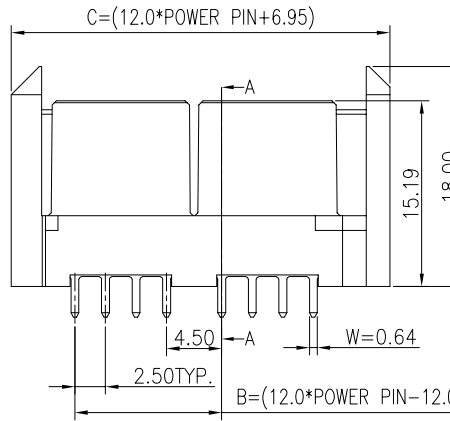
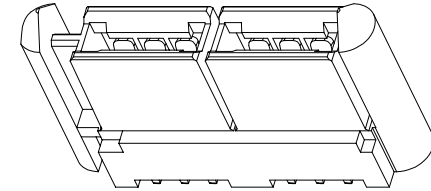
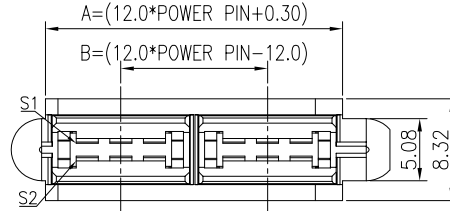
4.MAX PROCESSING TEMP:265°C SECONDS 10S

5.OPERATION TEMPERATURE:-40°C TO +105°C.

6.ORDER INFORMATION:

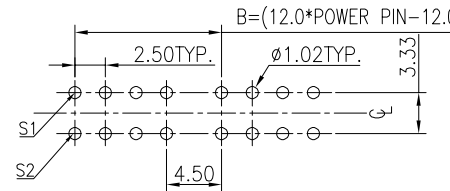
62F4V-F XXX S4 180 C 2X

		流水码:	
		21=2.31("P")	
电源Pin数	端子电镀:	塑胶高度:	22=2.51("P")
002=2*01PIN	S0=Gold Flash/Tin	180=18.00mm	23=3.06("P")
~	(半金锡)		
012=2*06PIN	S1=1u" Gold/Tin		
	S2=3u" Gold/Tin		
	S3=5u" Gold/Tin		
	S4=10u" Gold/Tin		
	S5=15u" Gold/Tin		
	S6=30u" Gold/Tin		



SECTION A-A

流水码	"P" 电源焊脚长度
21	2.31
22	2.51
23	3.06



RECOMMENDED PCB LAYOUT
PCB BOARD TOLERANCE±0.05

OPERATION

DRAW

Mr.Zeng

2025.03.17

SOLEPiN 东莞市硕品电子有限公司
PROFESSIONAL CONNECTOR DONGGUAN SOLEPIN ELECTRONICS CO., LTD.

X.X ±0.40

DESIGN

Jensen

2025.03.17

X.XX ±0.25

CHECK

Jack

2025.03.17

X.XXX ±0.15

APPROVE

Andy

2025.03.17

Angle ±3°

PROJ.

1/1

TITLE:

母座 电源连接器 立式180° 带导柱

DIM. TOL

UNIT

mm

SCALE

1:1

PROJ.

DRAW NO.

SP-1492

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
A0		NEW		